

Compal Confidential

VSKTA Schematics Document

Haswell ULT with DDR3L

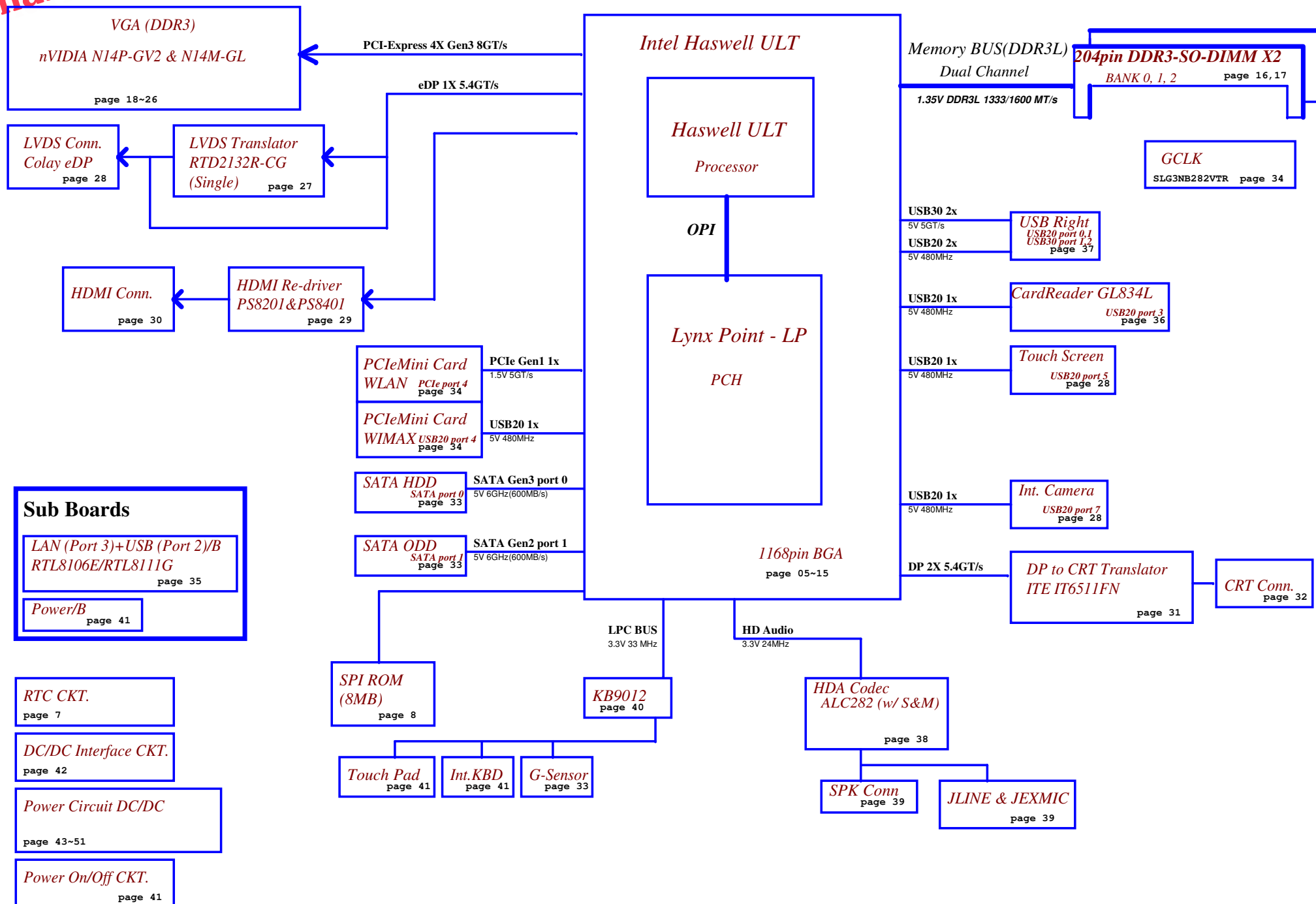
nVIDIA N14P-GV2 (Dual Rank)

nVIDIA N14M-GL

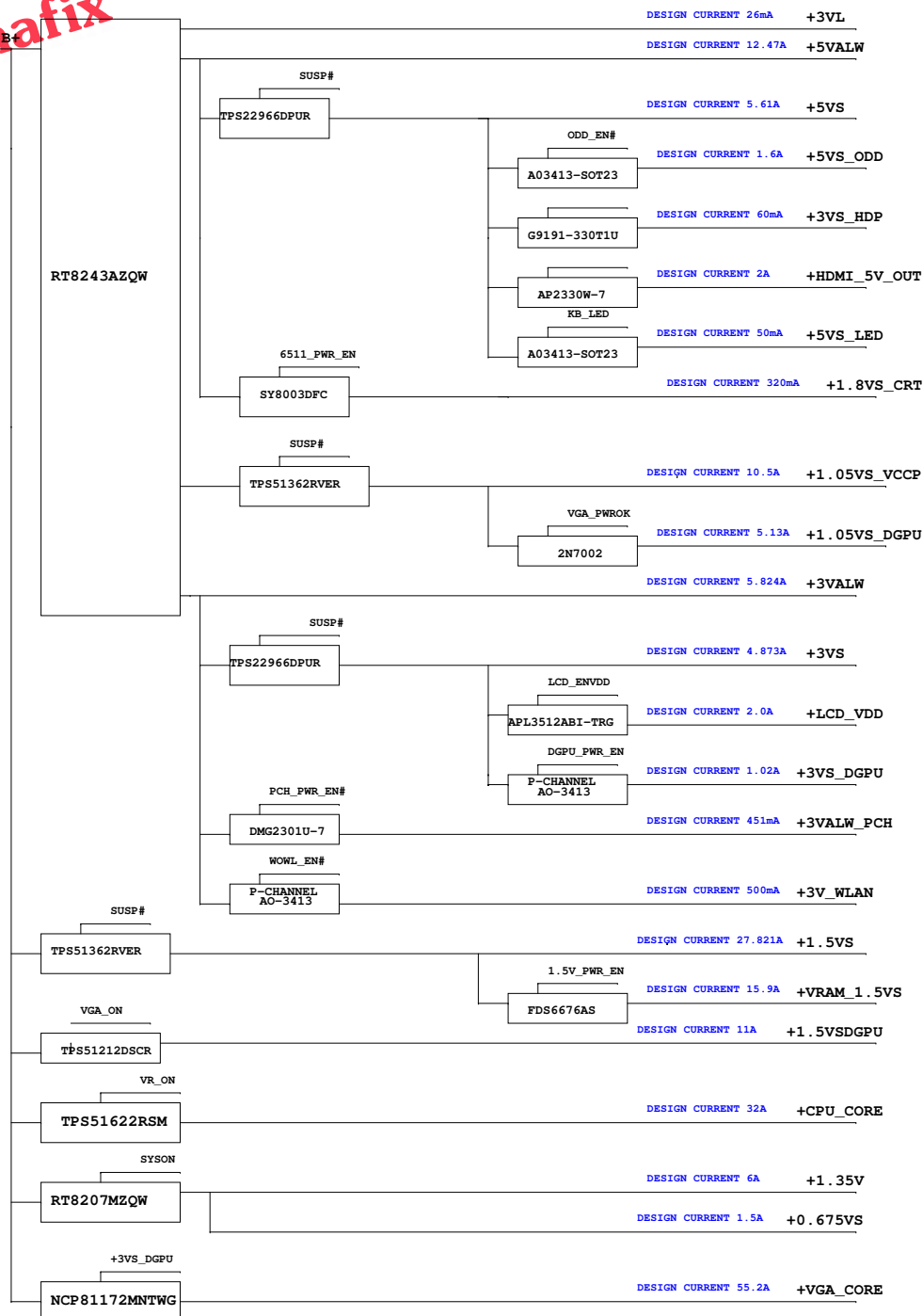
LA-9865P REV 2.0 Schematic

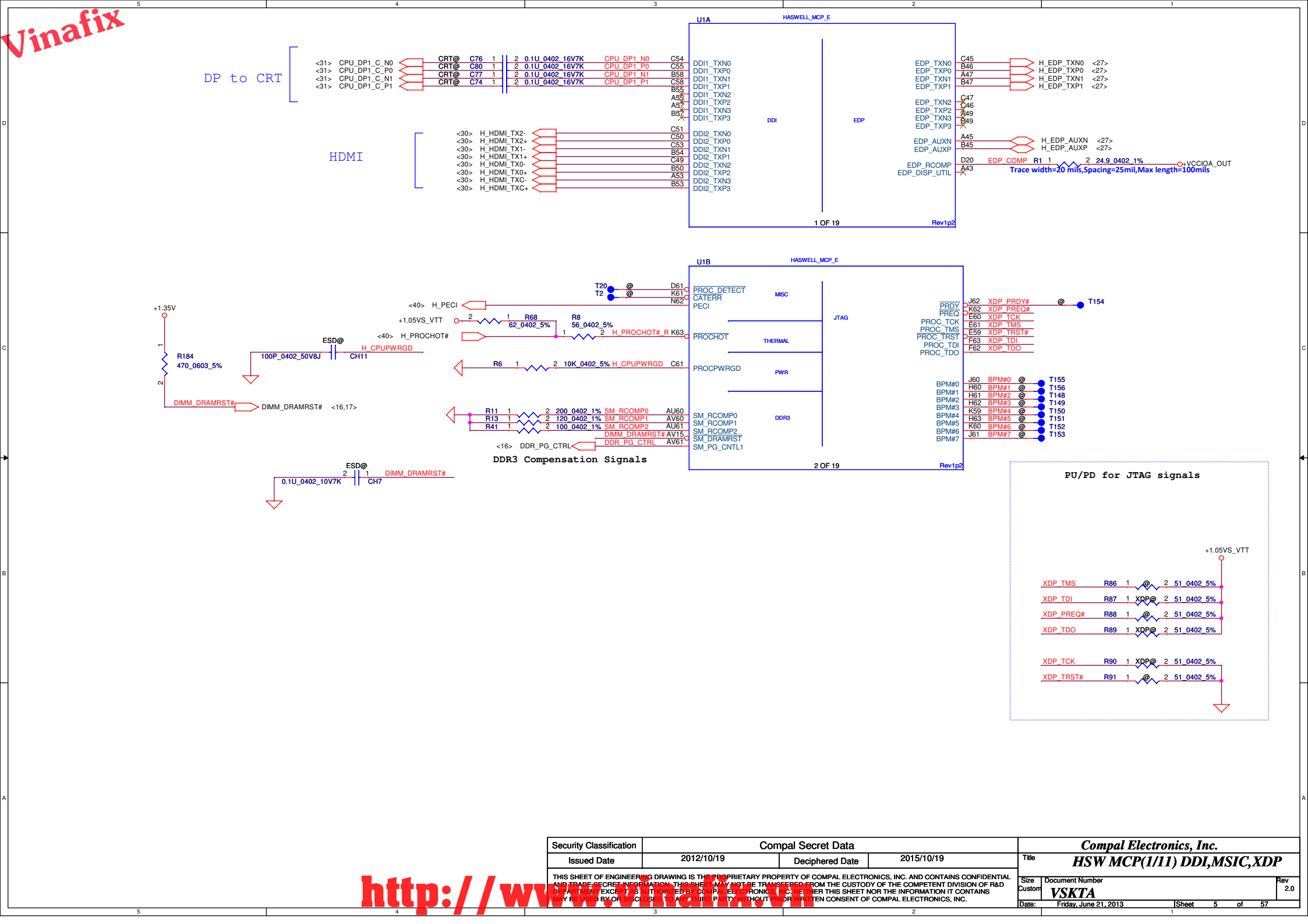
Intel Processor (Haswell)
2013-06-21 Rev 2.0

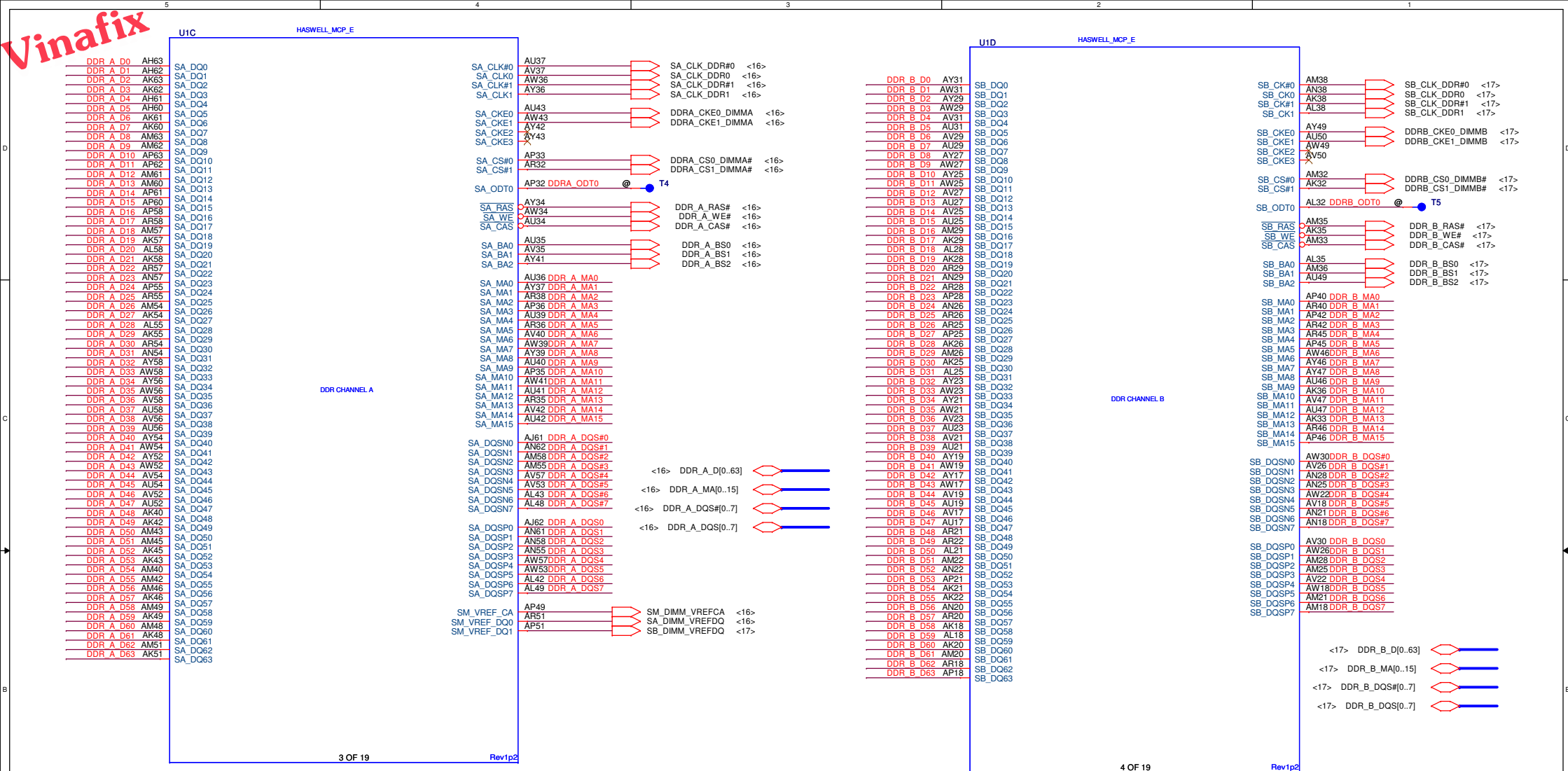
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Issued Date	2012/10/19	Deciphered Date	2015/10/19	Title	Cover Page
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				VSKTA	2.0
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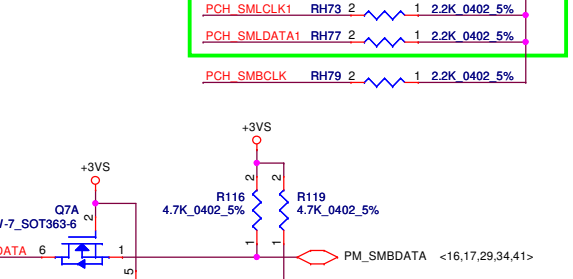
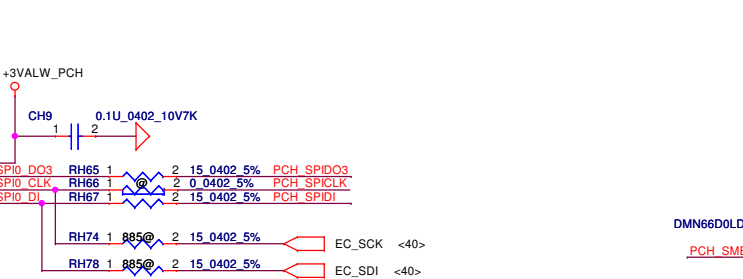
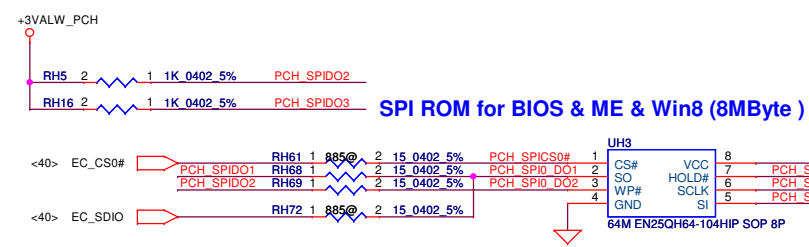
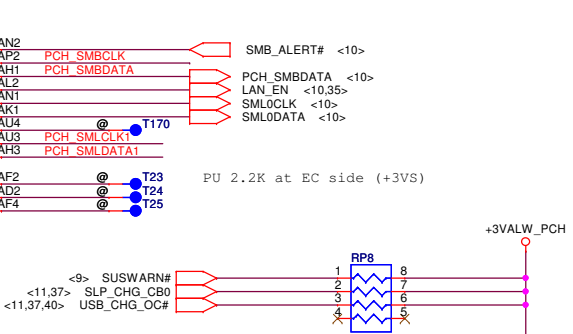
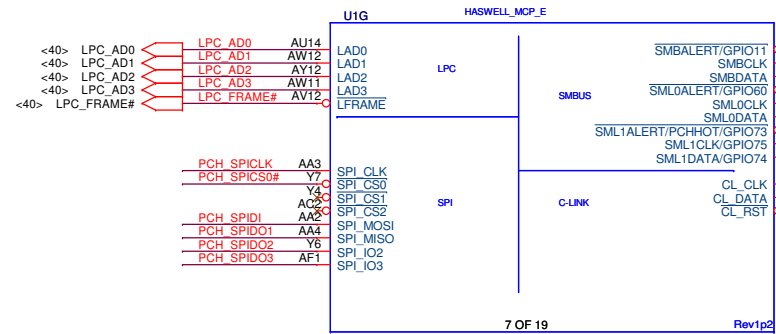
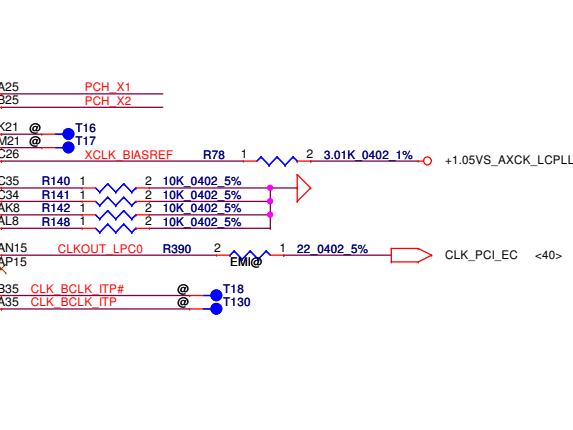
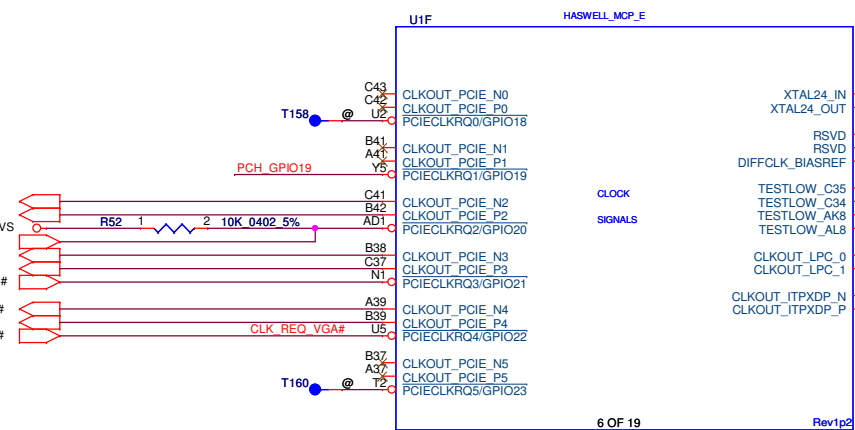
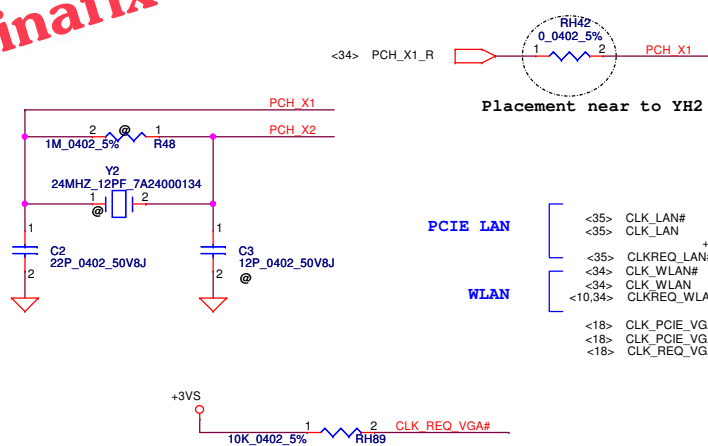


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								Block Diagram			
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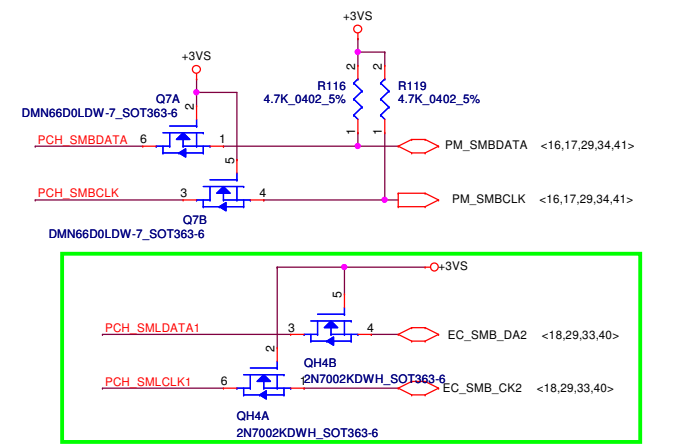






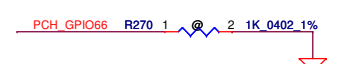
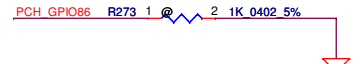
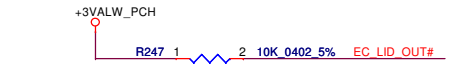
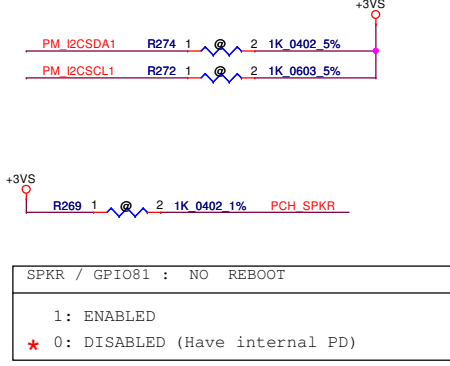
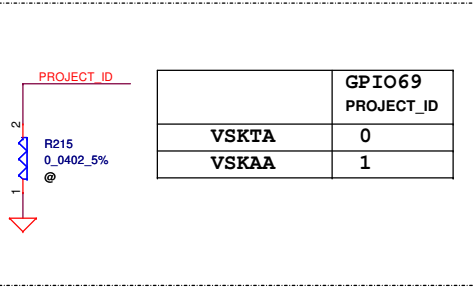
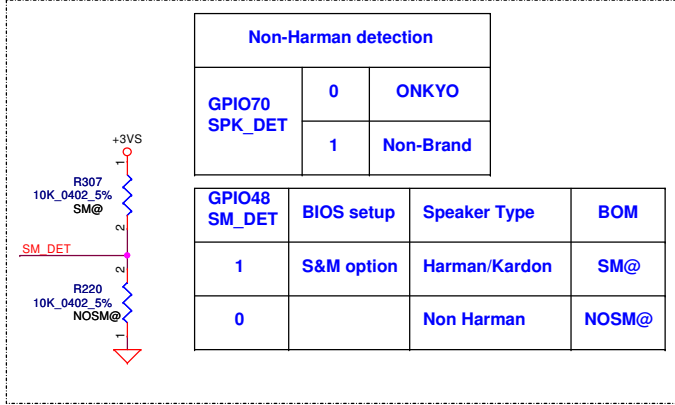
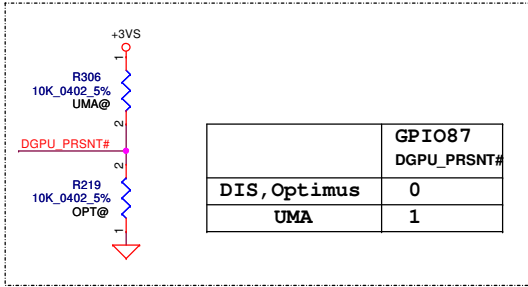
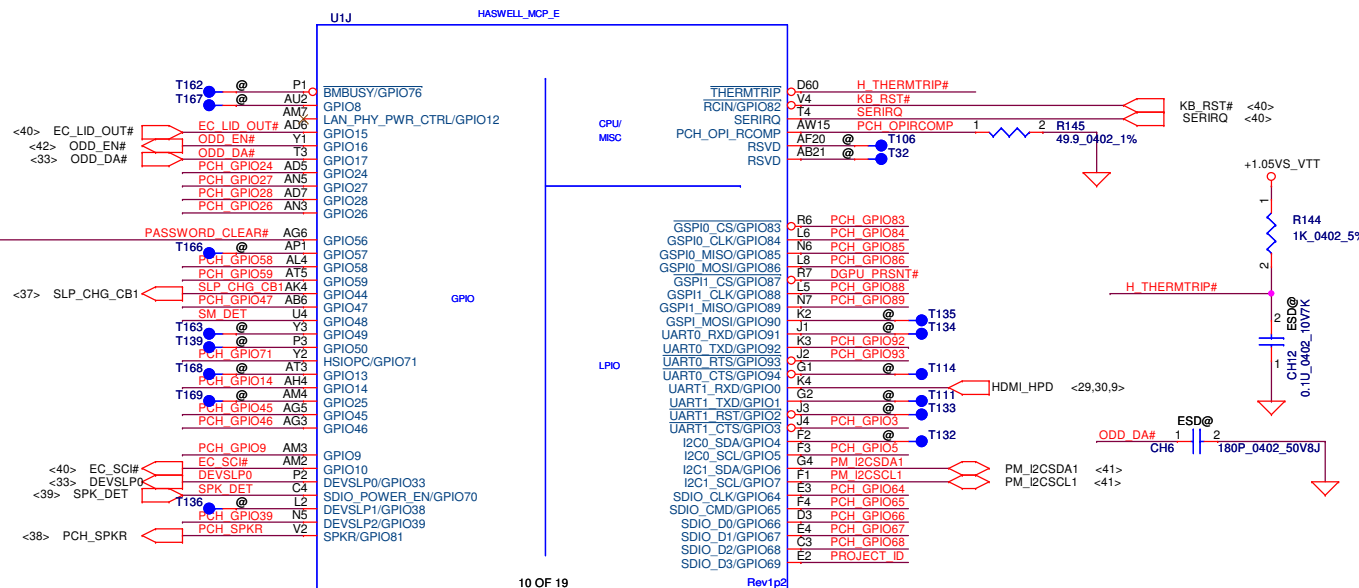
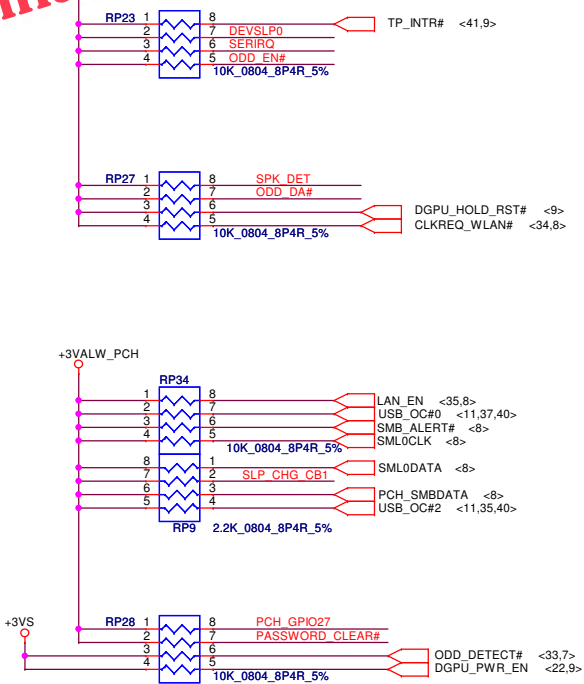


Please place UH3 close to U1 CPU,
Please place RH66, RH67, RH68 near UH3



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Note: need check all GPIO PU need or not after BIOS post



Non-Harman detection			
GPIO70 SPK_DET			
0	ONKYO		
1	Non-Brand		

GPIO48 SM_DET	BIOS setup	Speaker Type	BOM
1	S&M option	Harman/Kardon	SM@
0		Non Harman	NOSM@

PROJECT_ID		GPIO69 PROJECT_ID
VSKTA	0	
VSKAA	1	

SPKR / GPIO81 : NO REBOOT	
1: ENABLED	
* 0: DISABLED (Have internal PD)	

GPIO15 : TLS Confidentiality	
1: Intel ME TLS with confidentiality	
* 0: Intel ME TLS with no confidentiality (Have internal PD)	

GSPI0_MOSI / GPIO86 : Boot BIOS Strap	
1: ENABLED	
* 0: SPI ROM (Have internal PD)	

SDIO_D0 / GPIO66 : Top-Block Swap Override	
* 1: ENABLED (Have internal PU)	
0: DISABLED	

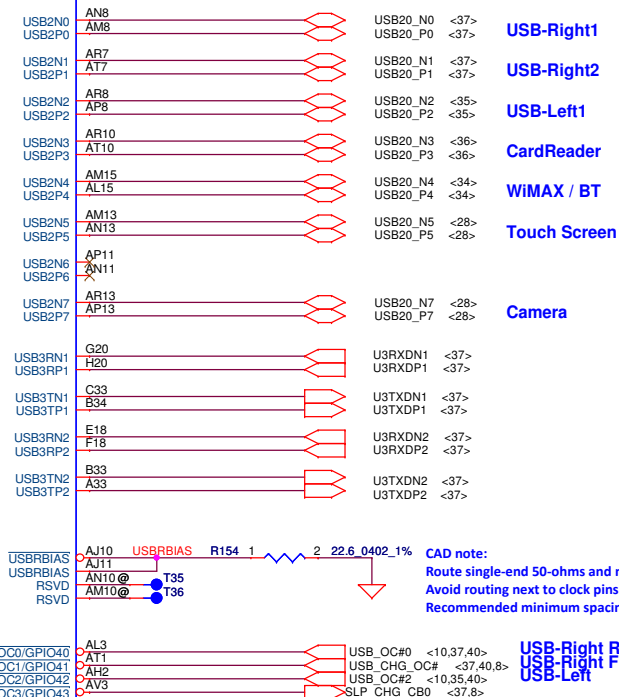
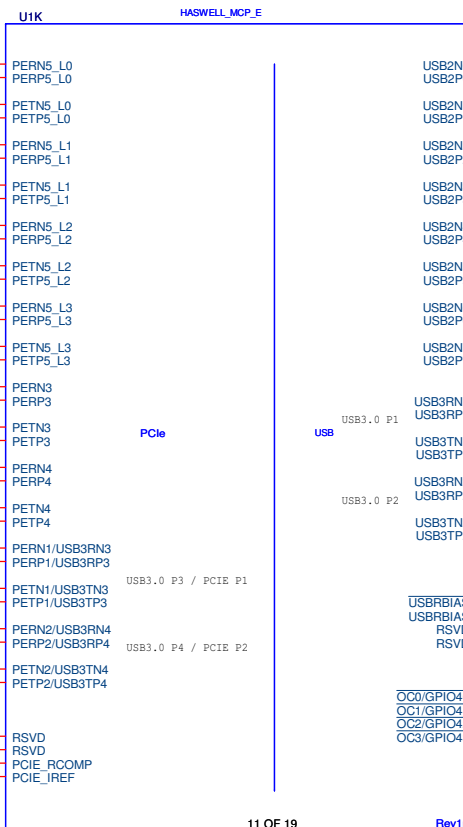
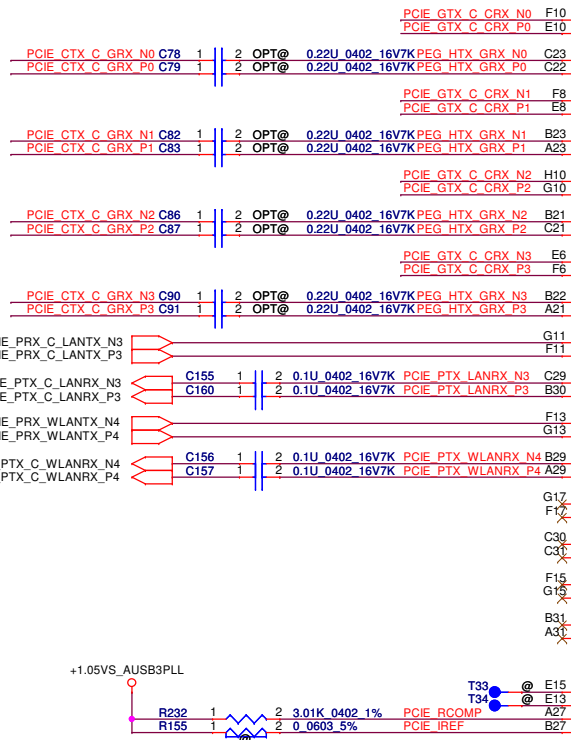
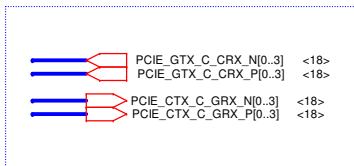
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Compal Electronics, Inc.	
HSW MCP(6/11) GPIO,LPIO	

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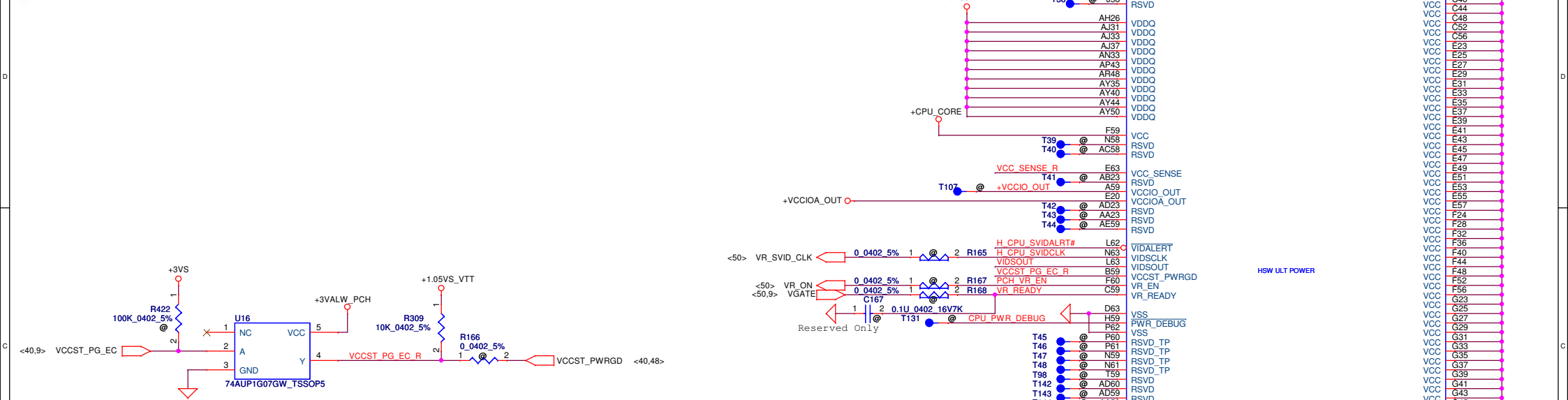
Vinafix



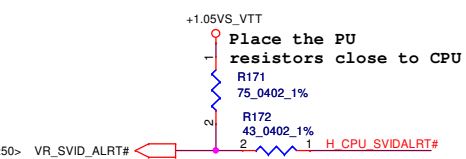
CAD note:
Route single-end 50-ohms and max 450-mils length.
Avoid routing next to clock pins or under stitching capacitors.
Recommended minimum spacing to other signal traces is 15 mils.

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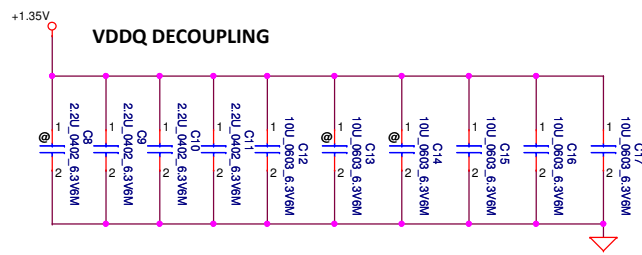
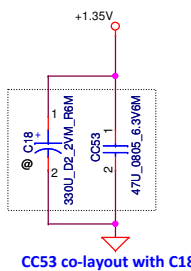
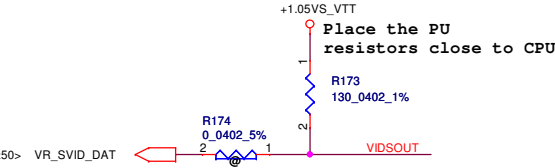
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SVID ALERT

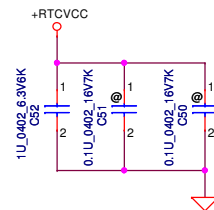
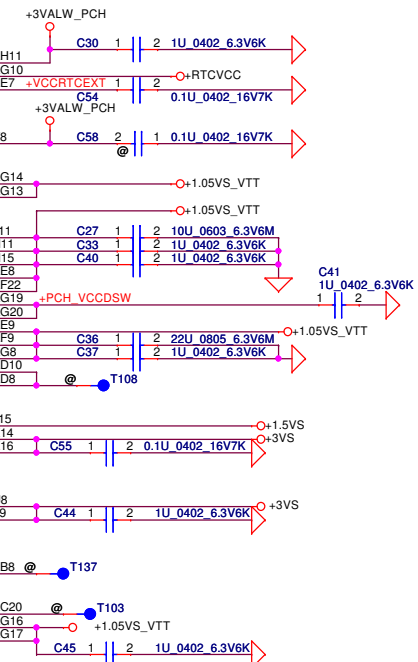
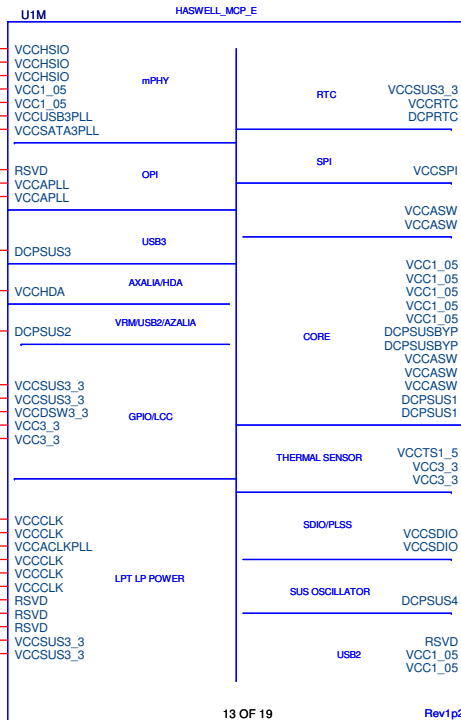
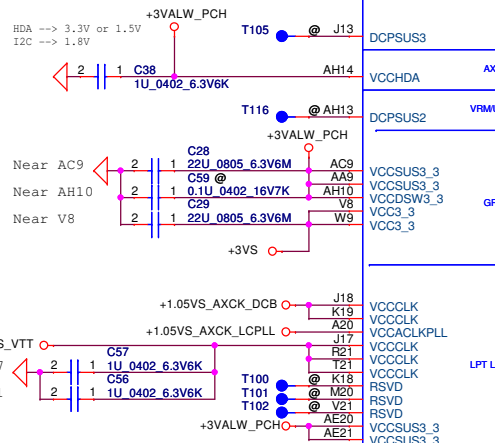
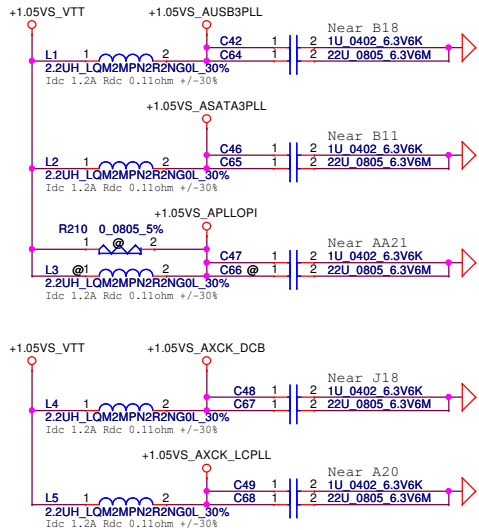
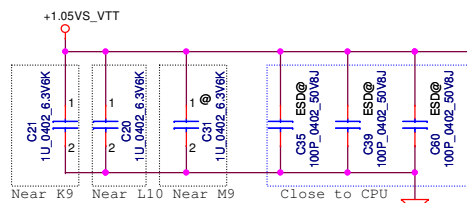


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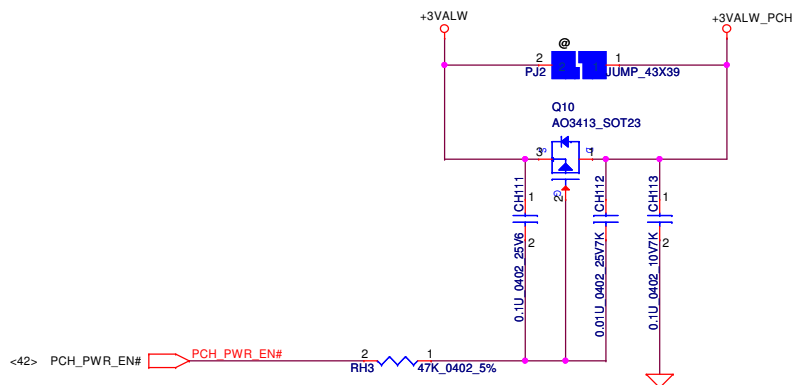


```
+1.35V : 470UF/2V/7343 *2
          10UF/6.3V/0603 * 6
          2.2UF/6.3V/0402 * 4
```

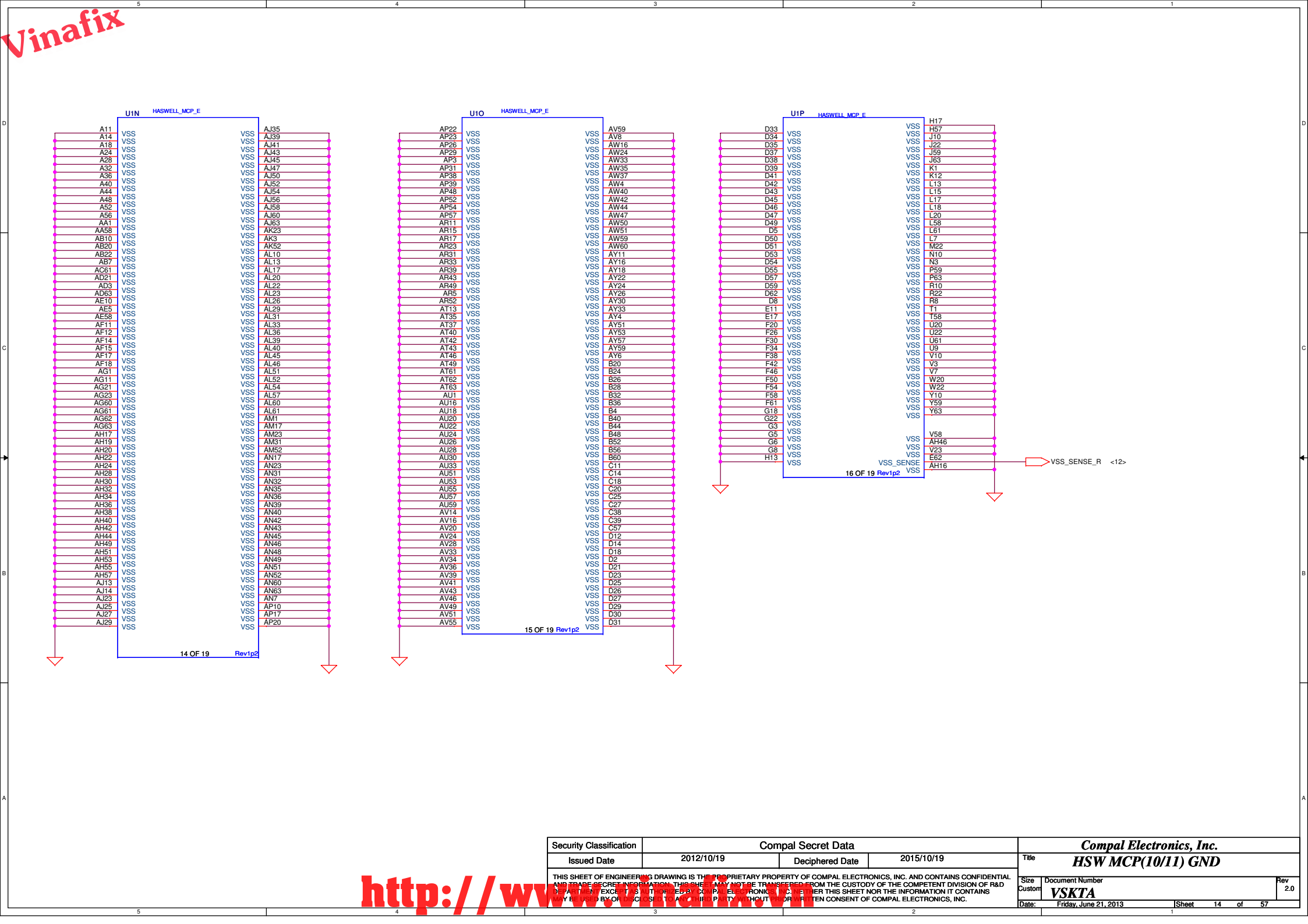
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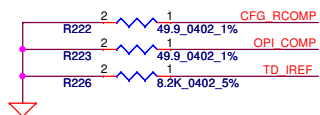
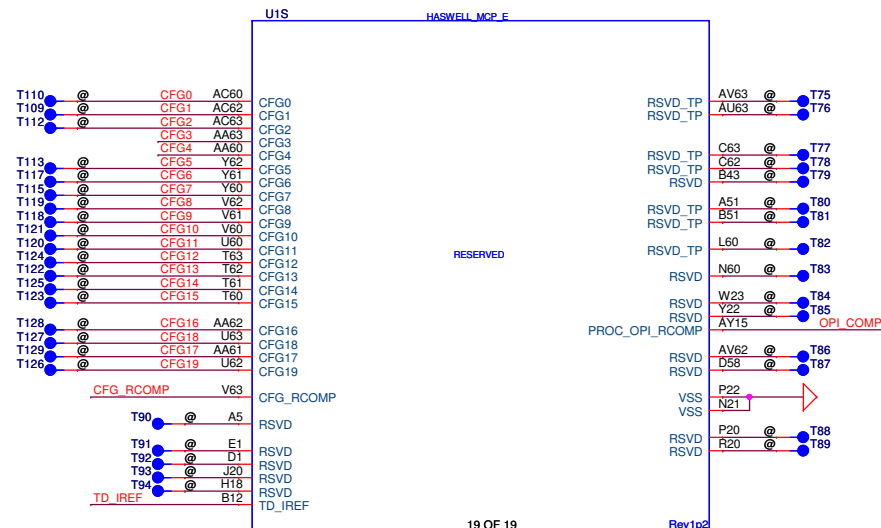
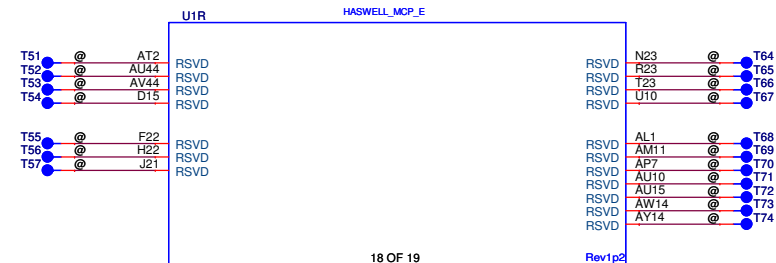
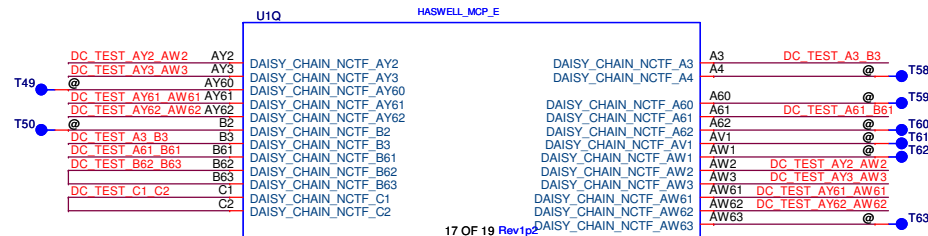


+3VALW to +3VALW_PCH

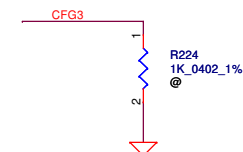


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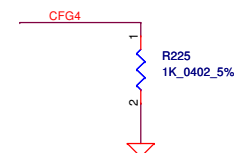




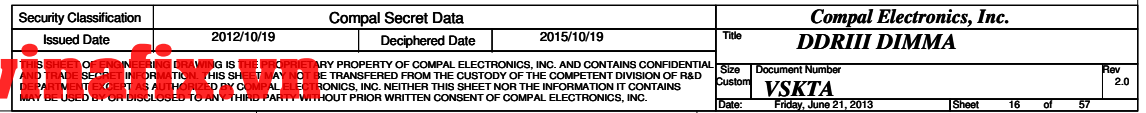
CFG Straps for Processor

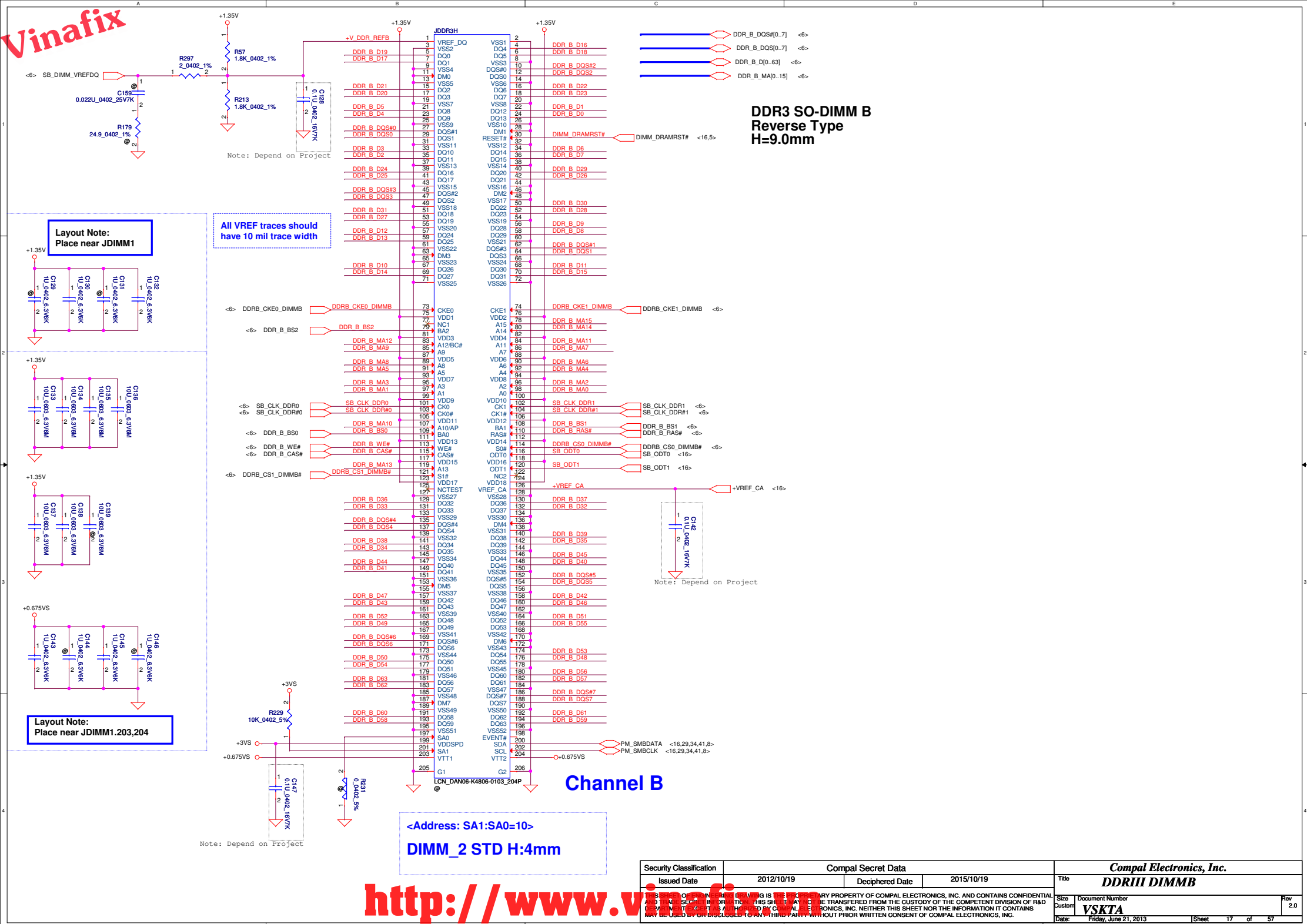


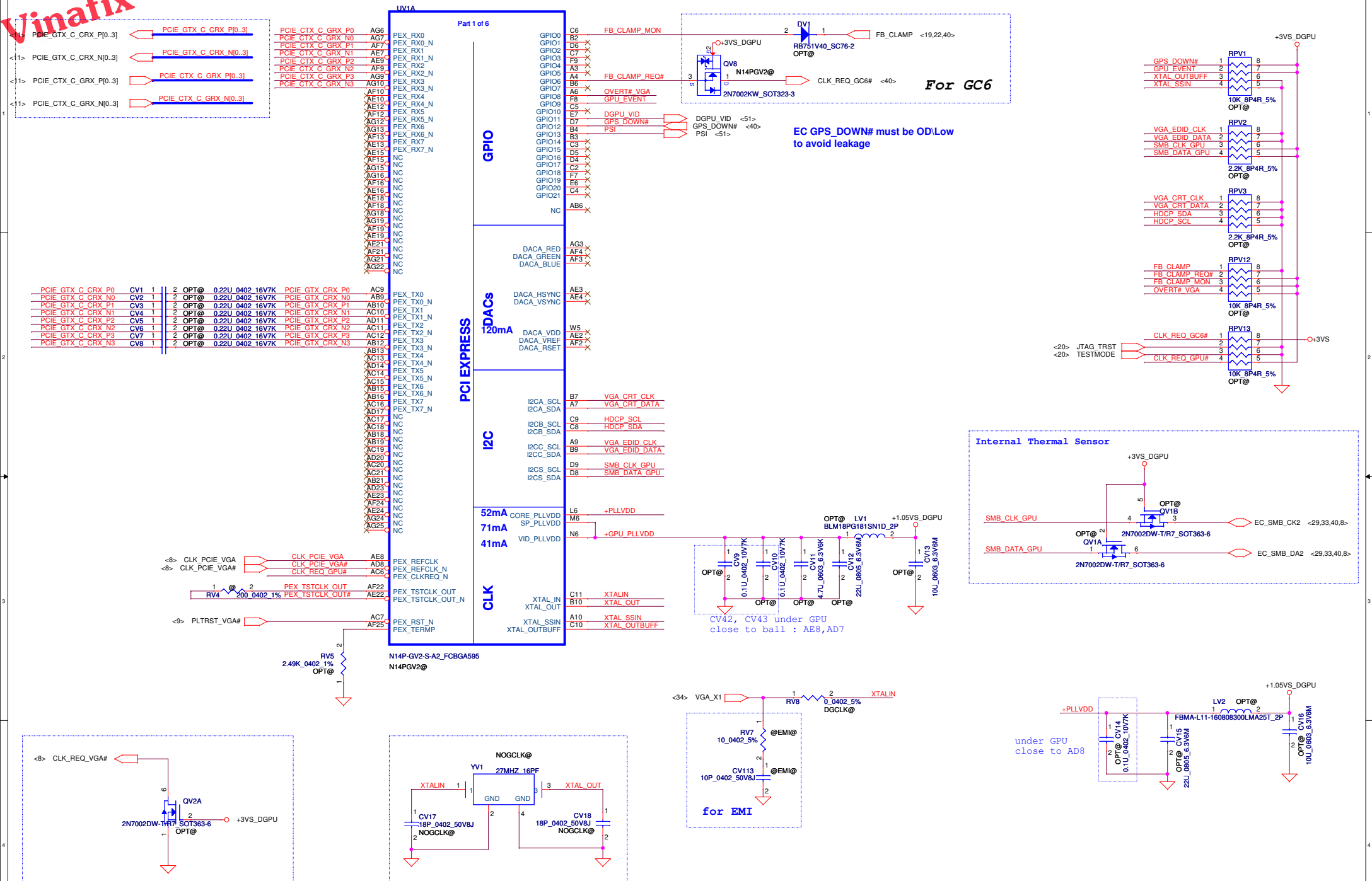
Physical Debug Enable (DFX Privacy)	
CFG3	1: DISABLED 0: ENABLED; SET DFX ENABLED BIT IN DEBUG INTERFACE MSR



Display Port Presence Strap	
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port 0 : Enabled; An external Display Port device is connected to the Embedded Display Port

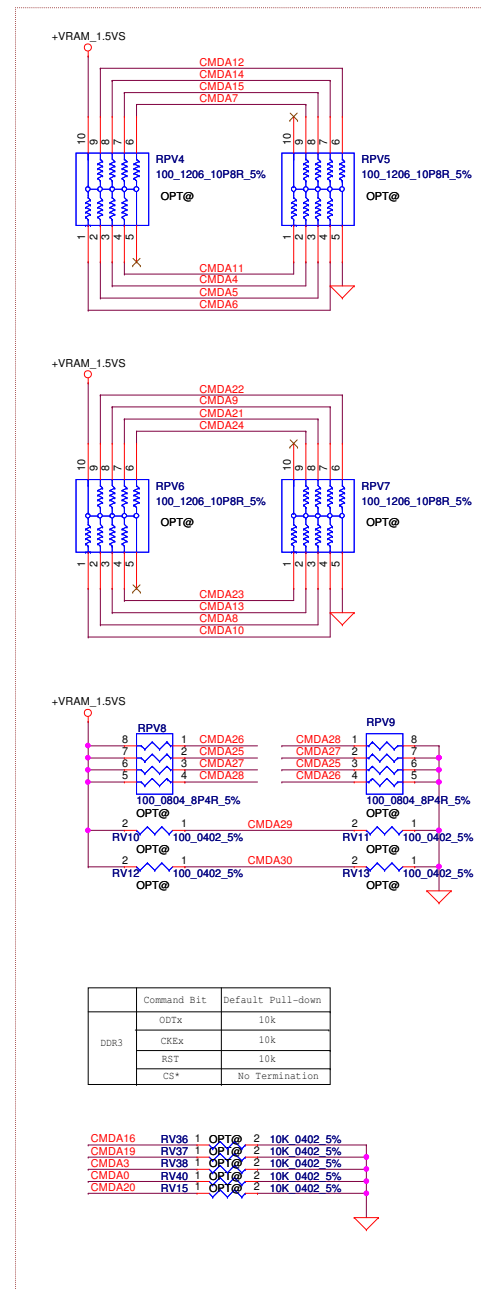
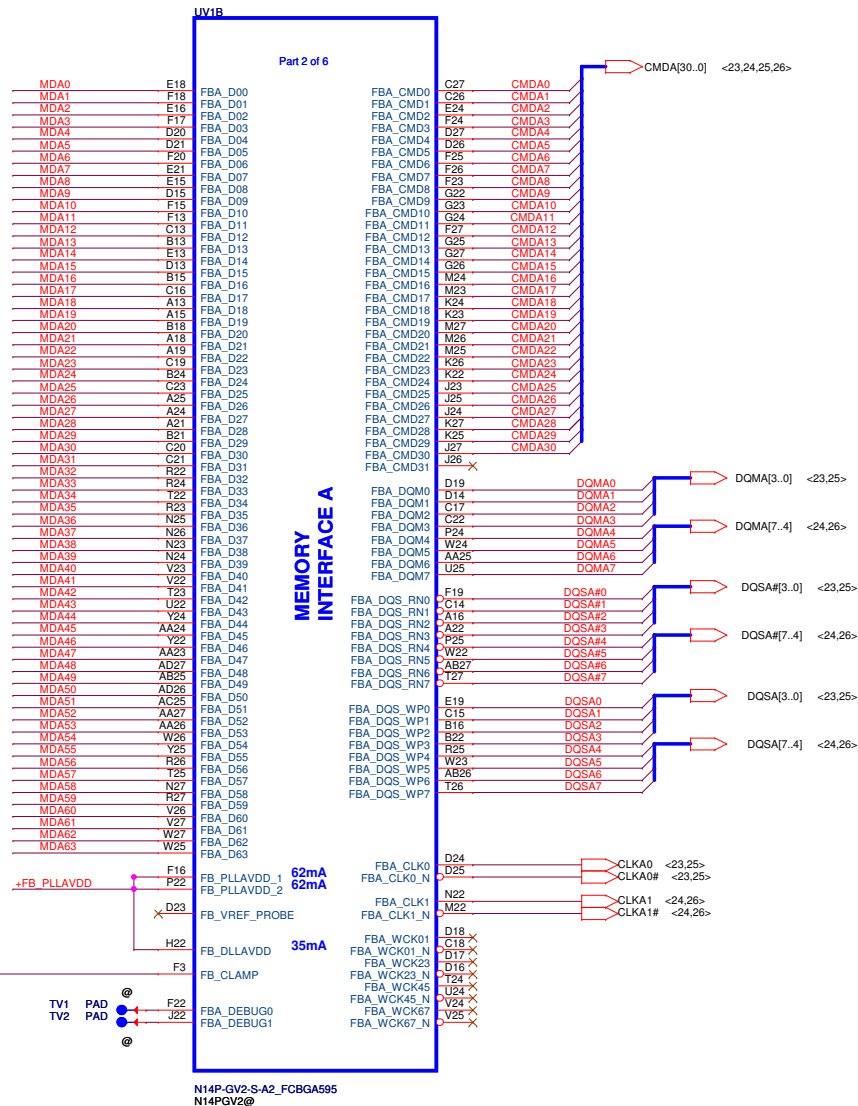






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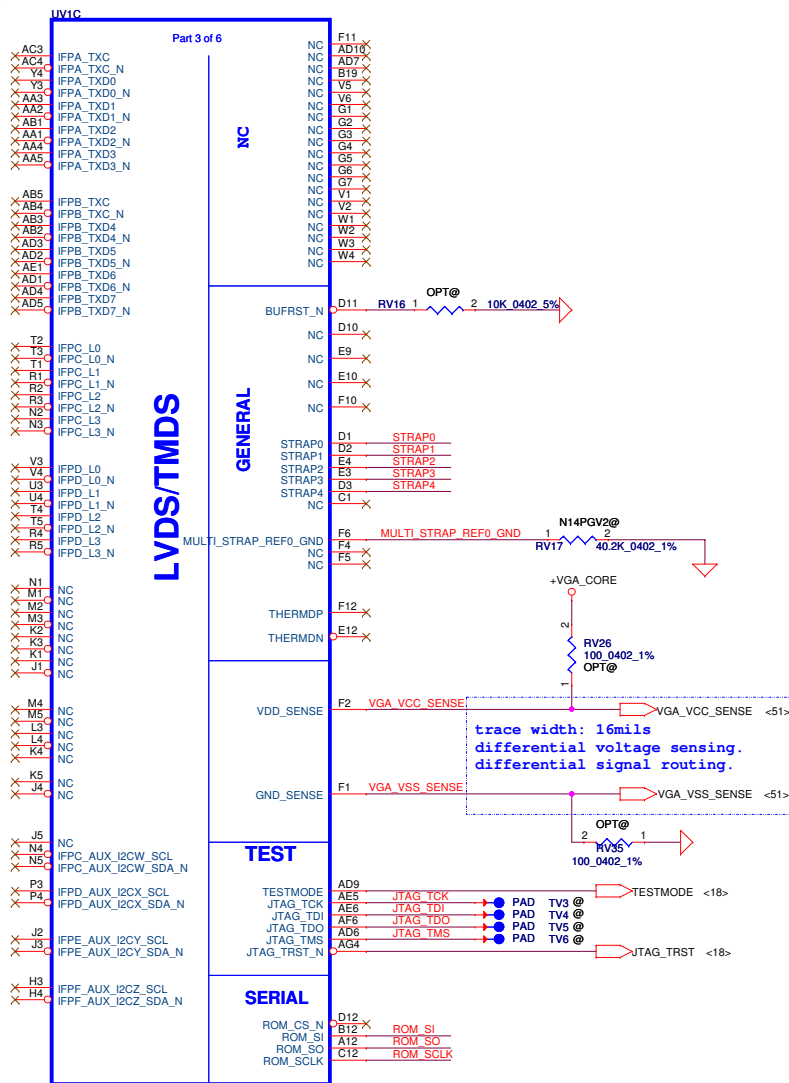
Place close to the first T point



	Command Bit	Default Pull-down
DDR3	ODTx	10k
	CKEx	10k
	RST	10k
	CS*	No Termination

CMDA16	RV36	1	OPT@	2	10K	0402	5%
CMDA19	RV37	1	OPT@	2	10K	0402	5%
CMDA3	RV38	1	OPT@	2	10K	0402	5%
CMDA0	RV40	1	OPT@	2	10K	0402	5%
CMDA20	RV15	1	OPT@	2	10K	0402	5%

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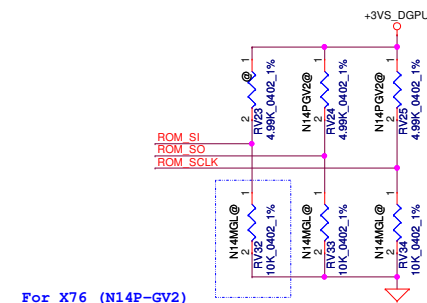
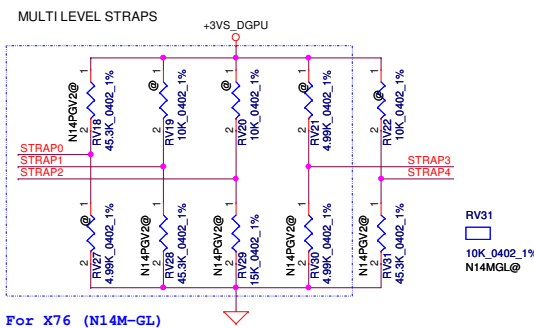


N14P-GV2-S-A2_FCBGA595
N14PGV2@

Physical Strapping pin	Power Rail	Logical Strapping Bit3	Logical Strapping Bit2	Logical Strapping Bit1	Logical Strapping Bit0
ROM_SO	+3VS_DGPU	FB[1]	FB[0]	SMB_ALT_ADDR	VGA_DEVICE
ROM_SCLK	+3VS_DGPU	PCI_DEVID[4]	SUB_VENDOR	PCI_DEVID[5]	PEX_PLLEN_TERM
ROM_SI	+3VS_DGPU	RAMCFG[3]	RAMCFG[2]	RAMCFG[1]	RAMCFG[0]
STRAP0	+3VS_DGPU	USER[3]	USER[2]	USER[1]	USER[0]
STRAP1	+3VS_DGPU	3GIO_PADCFG[3]	3GIO_PADCFG[2]	3GIO_PADCFG[1]	3GIO_PADCFG[0]
STRAP2	+3VS_DGPU	PCI_DEVID[3]	PCI_DEVID[2]	PCI_DEVID[1]	PCI_DEVID[0]
STRAP3	+3VS_DGPU	SOR3_EXPOSED	SOR2_EXPOSED	SOR1_EXPOSED	SOR0_EXPOSED
STRAP4	+3VS_DGPU	RESERVED	PCIE_SPEED_CHANGE_GEN3	PCIE_MAX_SPEED	DP_PLL_VDD33V

SKU	Device ID	bit5 to bit0
N14P-GV2	TBD	010010
N14M-GL	0x1140	000000

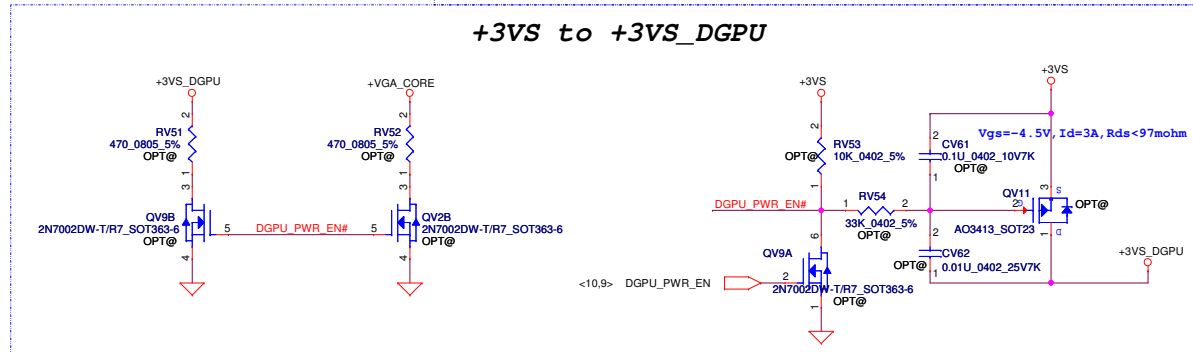
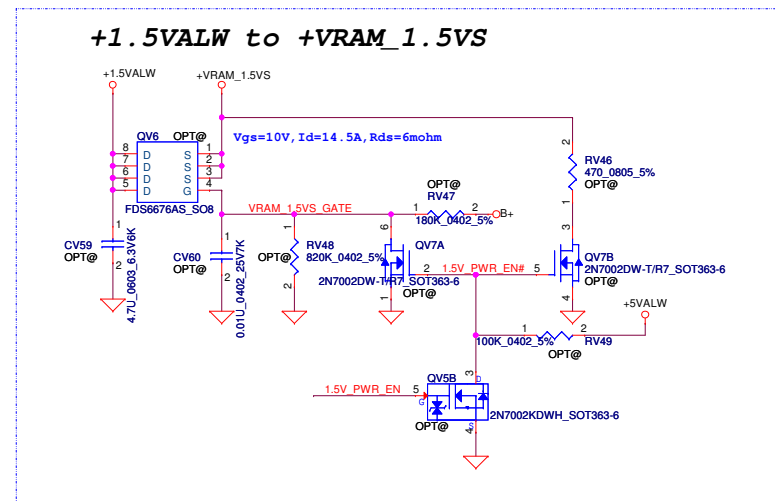
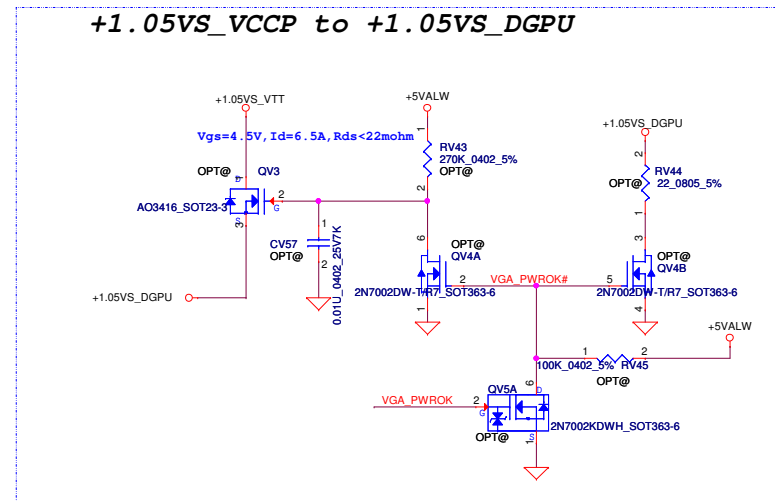
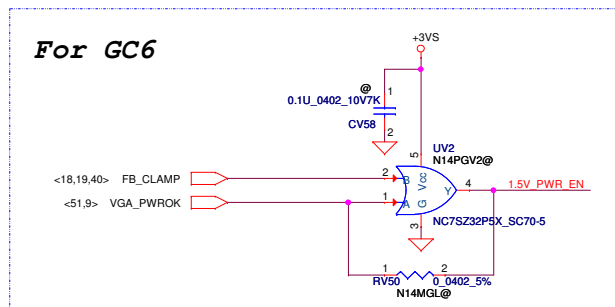
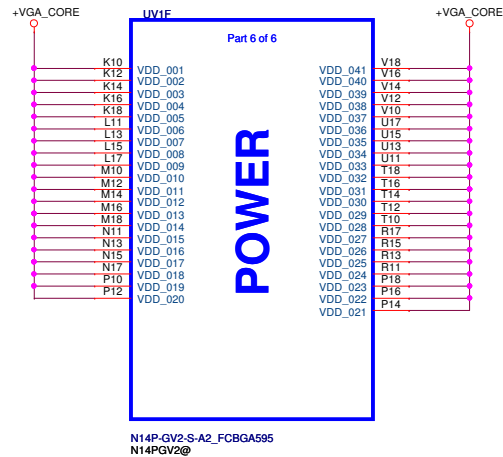
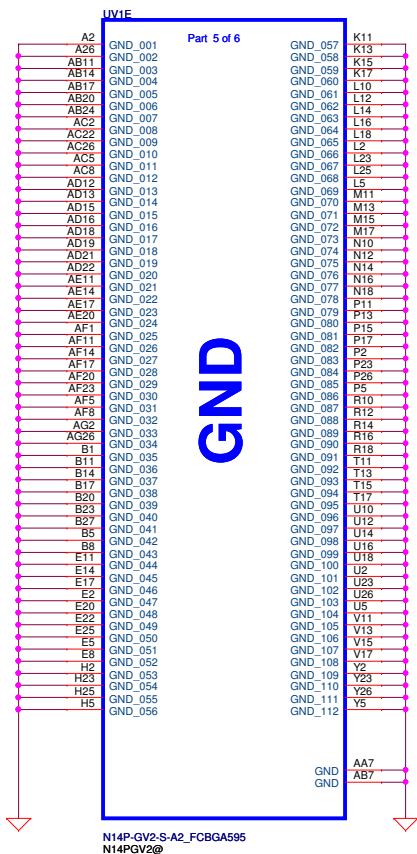
Resistor Values	Pull-up to +3VS_DGPU	Pull-down to Gnd
5K	1000	0000
10K	1001	0001
15K	1010	0010
20K	1011	0011
25K	1100	0100
30K	1101	0101
35K	1110	0110
45K	1111	0111



GPU	FB Memory gDDR3			ROM_SI	
N14P-GV2	1 2 8 M x 1 6	Samsung	900MHz	K4W2G1646E-BC11	PD 45K
			1GHz	K4W2G1646E-BC1A	
		Hynix	900MHz	H5TQ2G63DFR-11C	PD 34.8K
			1GHz	H5TQ2G63DFR-N0C	
		Micron	900MHz	MT41K128M16JT-107G	PD 30K
	2 5 6 M x 1 6	Samsung	900MHz	K4W4G1646B-BC11	PD 20K
		Micron	900MHz	MT41K256M16HA-107G	PD 10K

GPU	FB Memory gDDR3			STRAP [3:0]	
N14M-GL	1 2 8 M x 1 6	Samsung	900MHz	K4W2G1646E-BC11	0101
			1GHz	K4W2G1646E-BC1A	
		Hynix	900MHz	H5TQ2G63DFR-11C	0110
			1GHz	H5TQ2G63DFR-N0C	
		Micron	900MHz	MT41K128M16JT-107G	0001
	2 5 6 M x 1 6	Samsung	900MHz	K4W4G1646B-HC11	1011
		Hynix	900MHz	H5TC4G63AFR-11C	0100
Micron		900MHz	MT41K256M16HA-107G	1101	

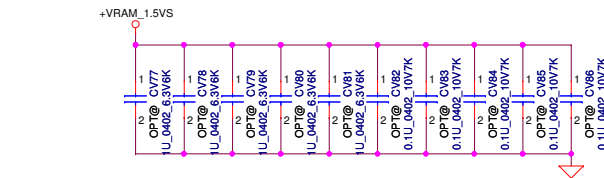
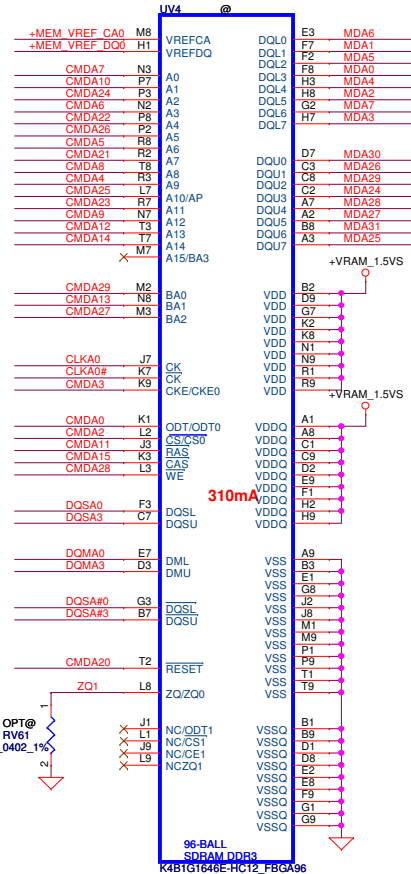
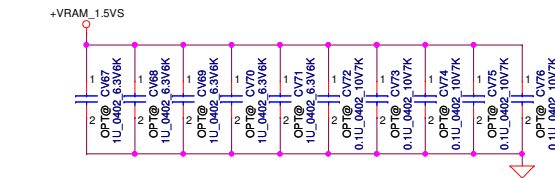
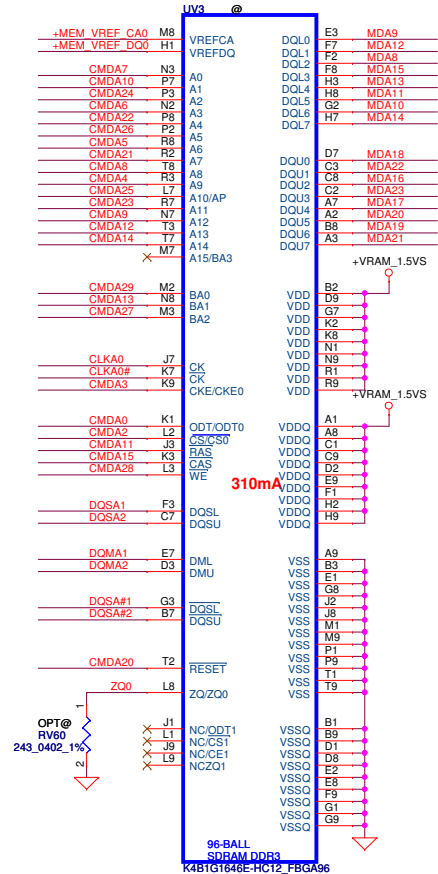
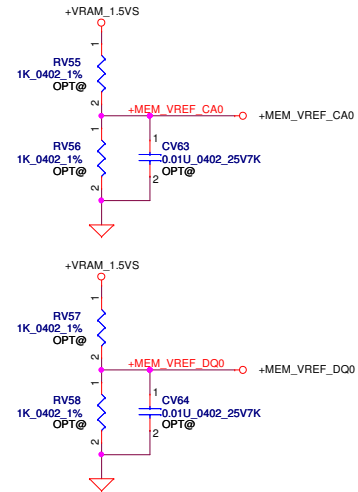
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Date: Friday, June 21, 2013				Sheet 20 of 57



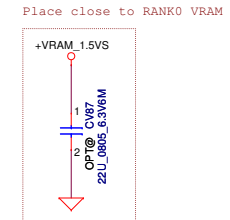
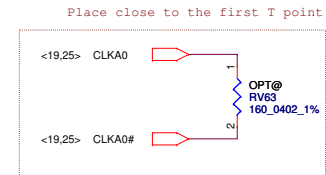
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Rev 2.0				Date: Friday, June 21, 2013
Sheet 22 of 57				

RANK 0 [31...0] VRAM DDR3 Chips

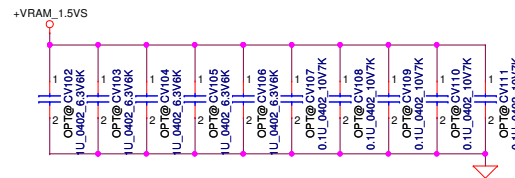
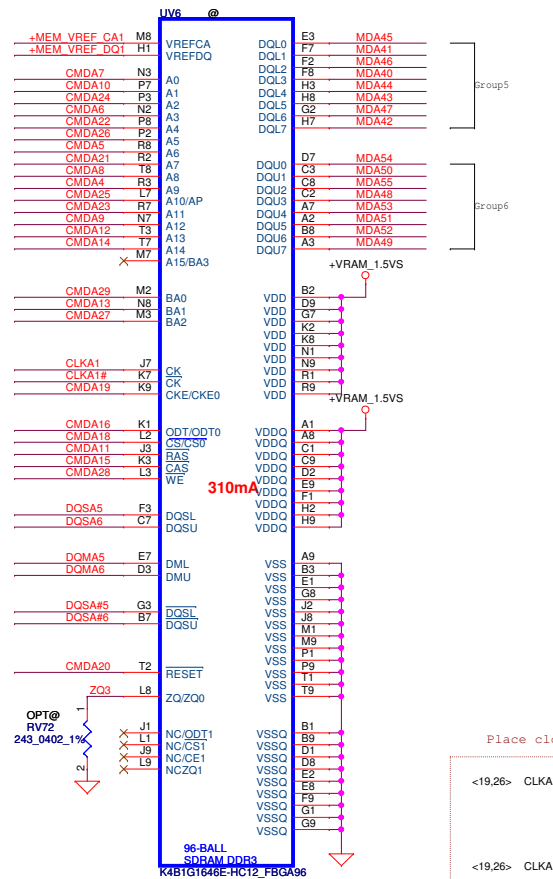
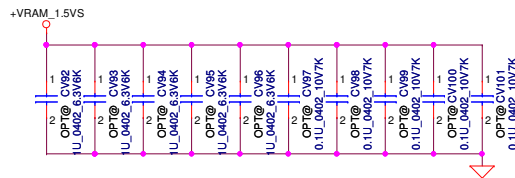
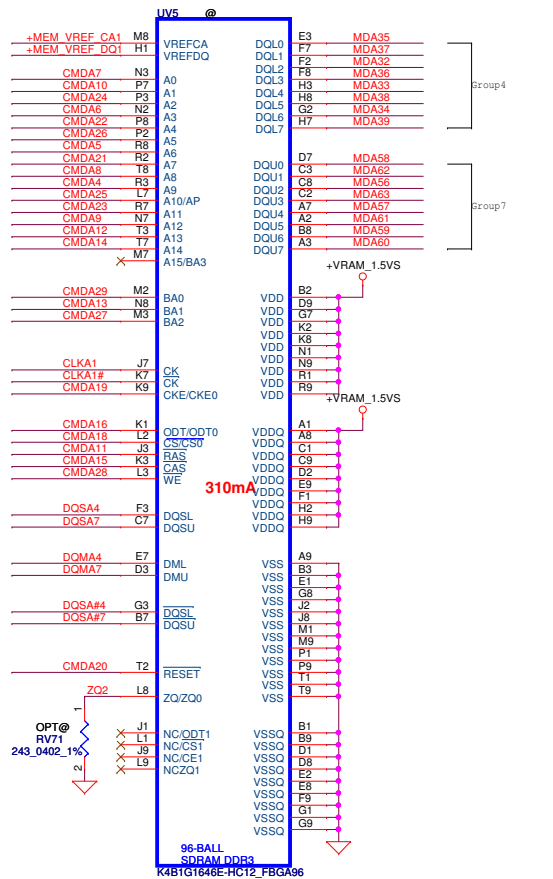
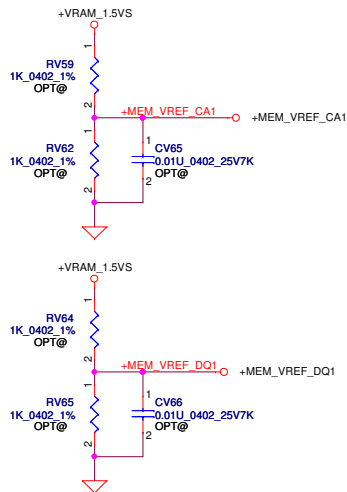
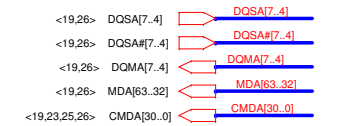
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<19,25> DQMA[3..0] → DQMA[3..0]
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<19,24,25,26> CMDA[30..0] → CMDA[30..0]



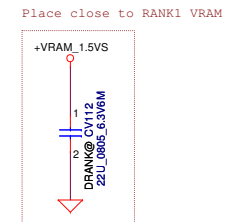
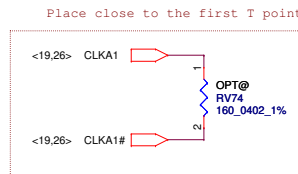
Mode E Address	Rank 0		Rank 1	
	0..31	32..63	0..31	32..63
CMD0	ODT		ODT	
CMD1			CS1#	
CMD2	CS0#			
CMD3	CKE		CKE	
CMD4	A9	A9	A11	A11
CMD5	A6	A6	A7	A7
CMD6	A3	A3	BA1	BA1
CMD7	A0	A0	A12	A12
CMD8	A8	A8	A8	A8
CMD9	A12	A12	A0	A0
CMD10	A1	A1	A2	A2
CMD11	RAS#	RAS#	RAS#	RAS#
CMD12	A13	A13	A14	A14
CMD13	BA1	BA1	A3	A3
CMD14	A14	A14	A13	A13
CMD15	CAS#	CAS#	CAS#	CAS#
CMD16		ODT		ODT
CMD17			CS1#	
CMD18		CS0#		
CMD19		CKE		CKE
CMD20	RST	RST	RST	RST
CMD21	A7	A7	A6	A6
CMD22	A4	A4	A5	A5
CMD23	A11	A11	A9	A9
CMD24	A2	A2	A1	A1
CMD25	A10	A10	WE#	WE#
CMD26	A5	A5	A4	A4
CMD27	BA2	BA2		
CMD28	WE#	WE#	A10	A10
CMD29	BA0	BA0	BA0	BA0
CMD30			BA2	BA2



RANK 0 [63..32] VRAM DDR3 Chips



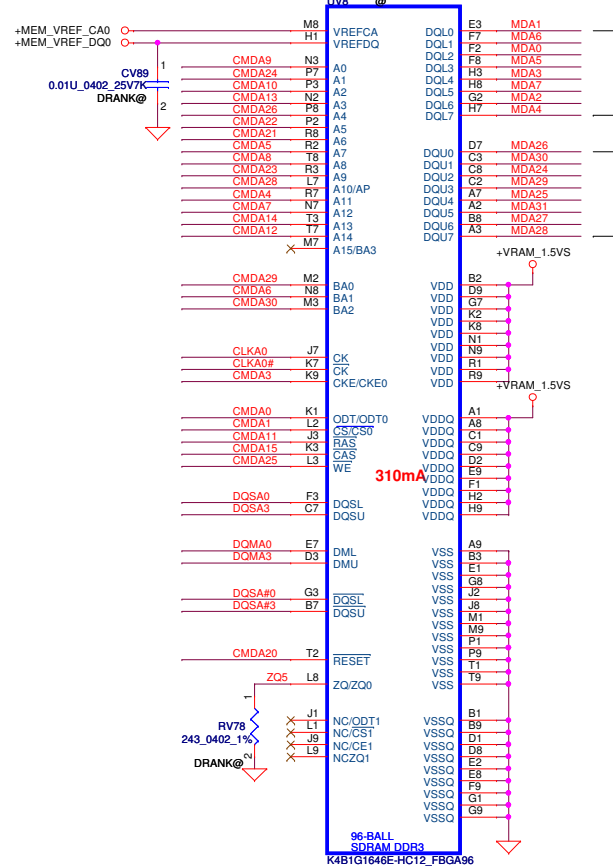
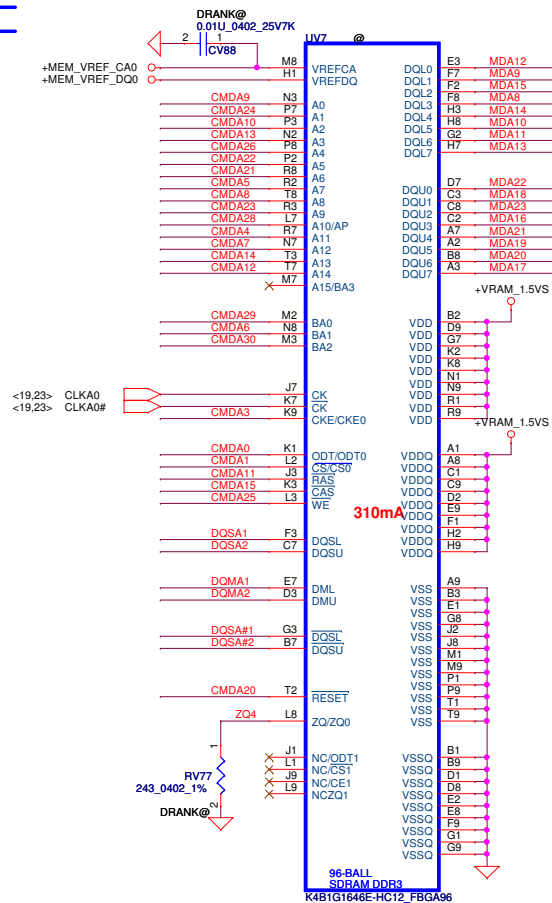
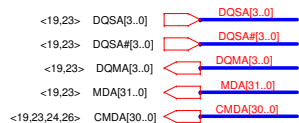
Mode E Address	Rank 0		Rank 1	
	0..31	32..63	0..31	32..63
CMD0	ODT		ODT	
CMD1			CS1#	
CMD2	CS0#			
CMD3	CKE		CKE	
CMD4	A9	A9	A11	A11
CMD5	A6	A6	A7	A7
CMD6	A3	A3	BA1	BA1
CMD7	A0	A0	A12	A12
CMD8	A8	A8	A8	A8
CMD9	A12	A12	A0	A0
CMD10	A1	A1	A2	A2
CMD11	RAS#	RAS#	RAS#	RAS#
CMD12	A13	A13	A14	A14
CMD13	BA1	BA1	A3	A3
CMD14	A14	A14	A13	A13
CMD15	CAS#	CAS#	CAS#	CAS#
CMD16		ODT		ODT
CMD17			CS1#	
CMD18		CS0#		
CMD19		CKE	CKE	
CMD20	RST	RST	RST	RST
CMD21	A7	A7	A6	A6
CMD22	A4	A4	A5	A5
CMD23	A11	A11	A9	A9
CMD24	A2	A2	A1	A1
CMD25	A10	A10	WE#	WE#
CMD26	A5	A5	A4	A4
CMD27	BA2	BA2		
CMD28	WE#	WE#	A10	A10
CMD29	BA0	BA0	BA0	BA0
CMD30			BA2	BA2



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				VGA N14x VRAM RANK 0H	2.0
				Date: Friday, June 21, 2013	Sheet 24 of 57

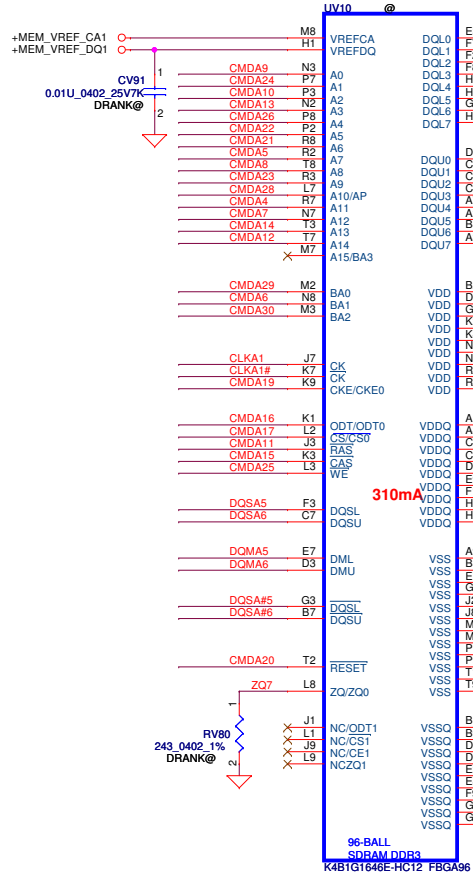
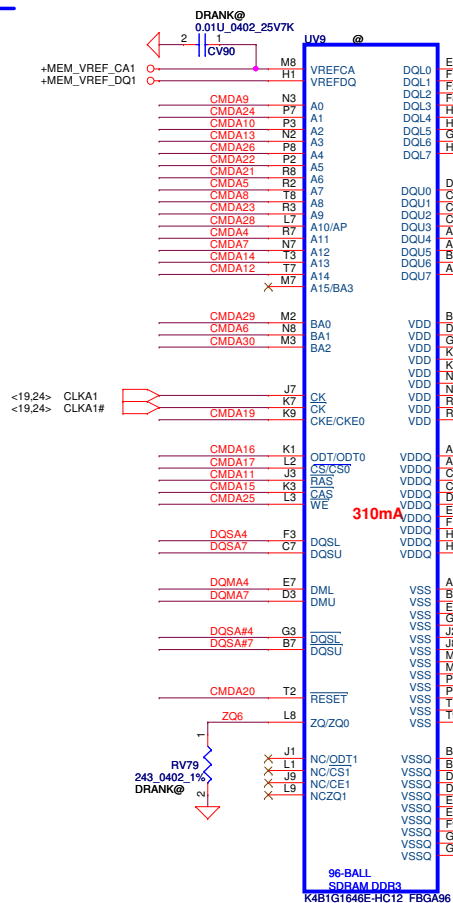
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VRAM DDR3 Chips



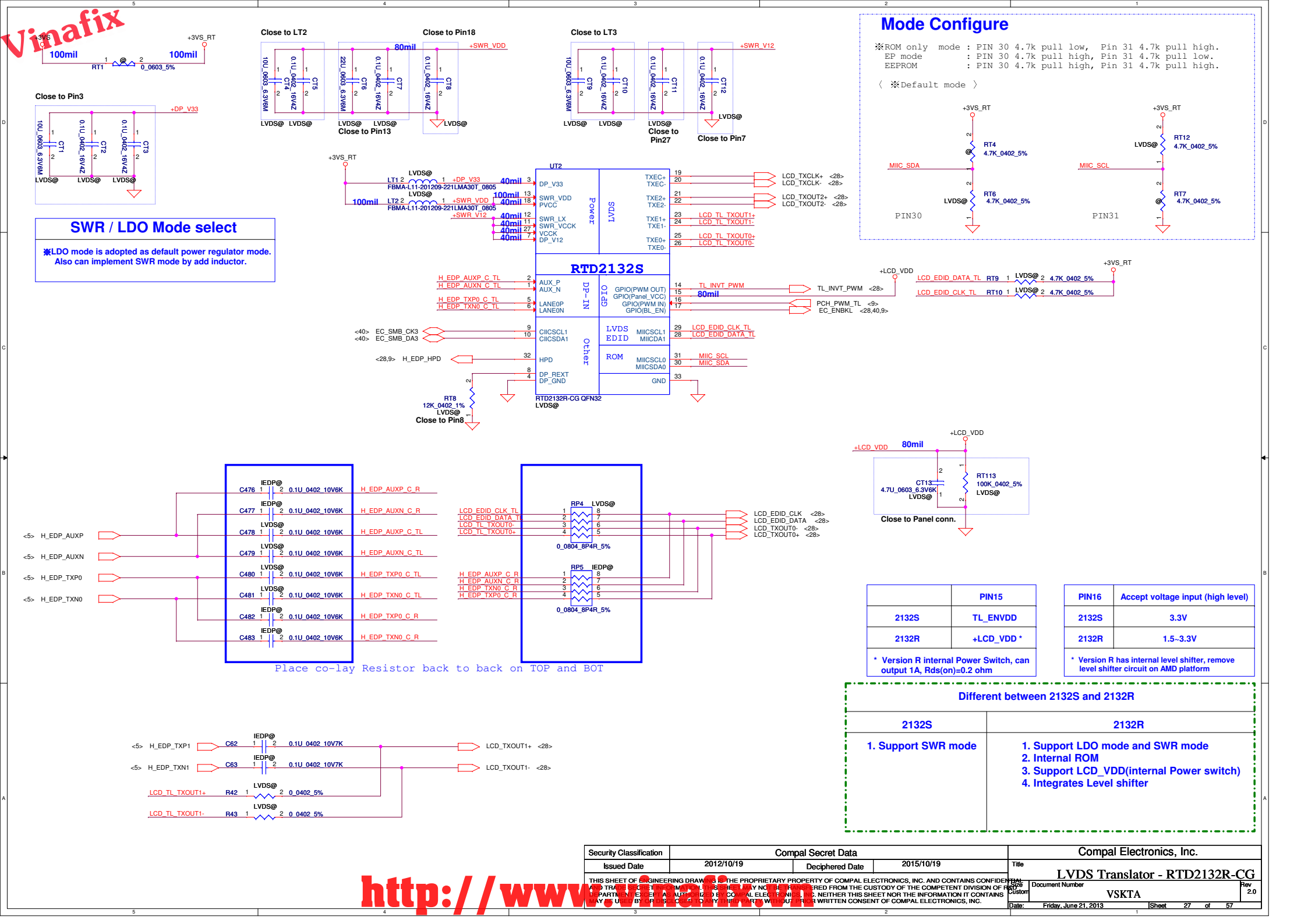
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	0..31	32..63	0..31	32..63
CMD0	ODT		ODT	
CMD1			CS1#	
CMD2	CS0#			
CMD3	CKE		CKE	
CMD4	A9	A9	A11	A11
CMD5	A6	A6	A7	A7
CMD6	A3	A3	BA1	BA1
CMD7	A0	A0	A12	A12
CMD8	A8	A8	A8	A8
CMD9	A12	A12	A0	A0
CMD10	A1	A1	A2	A2
CMD11	RAS#	RAS#	RAS#	RAS#
CMD12	A13	A13	A14	A14
CMD13	BA1	BA1	A3	A3
CMD14	A14	A14	A13	A13
CMD15	CAS#	CAS#	CAS#	CAS#
CMD16		ODT		ODT
CMD17				CS1#
CMD18		CS0#		
CMD19		CKE		CKE
CMD20	RST	RST	RST	RST
CMD21	A7	A7	A6	A6
CMD22	A4	A4	A5	A5
CMD23	A11	A11	A9	A9
CMD24	A2	A2	A1	A1
CMD25	A10	A10	WE#	WE#
CMD26	A5	A5	A4	A4
CMD27	BA2	BA2		
CMD28	WE#	WE#	A10	A10
CMD29	BA0	BA0	BA0	BA0
CMD30			BA2	BA2

RANK 1 [63...32] VRAM DDR3 Chips

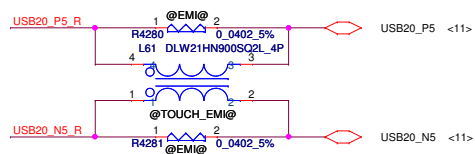
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<19,24> DQSA# [7..4] → DQSA# [7..4]
<19,24> DQMA[7..4] → DQMA[7..4]
<19,24> MDA[63..32] → MDA[63..32]
<19,23,24,25> CMDA[30..0] → CMDA[30..0]



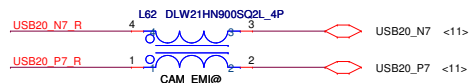
Mode E Address	Rank 0		Rank 1	
	0..31	32..63	0..31	32..63
CMD0	ODT		ODT	
CMD1			CS1#	
CMD2	CS0#			
CMD3	CKE		CKE	
CMD4	A9	A9	A11	A11
CMD5	A6	A6	A7	A7
CMD6	A3	A3	BA1	BA1
CMD7	A0	A0	A12	A12
CMD8	A8	A8	A8	A8
CMD9	A12	A12	A0	A0
CMD10	A1	A1	A2	A2
CMD11	RAS#	RAS#	RAS#	RAS#
CMD12	A13	A13	A14	A14
CMD13	BA1	BA1	A3	A3
CMD14	A14	A14	A13	A13
CMD15	CAS#	CAS#	CAS#	CAS#
CMD16		ODT		ODT
CMD17			CS1#	
CMD18		CS0#		
CMD19		CKE		CKE
CMD20	RST	RST	RST	RST
CMD21	A7	A7	A6	A6
CMD22	A4	A4	A5	A5
CMD23	A11	A11	A9	A9
CMD24	A2	A2	A1	A1
CMD25	A10	A10	WE#	WE#
CMD26	A5	A5	A4	A4
CMD27	BA2	BA2		
CMD28	WE#	WE#	A10	A10
CMD29	BA0	BA0	BA0	BA0
CMD30			BA2	BA2



BTO : TOUCH_EMI@

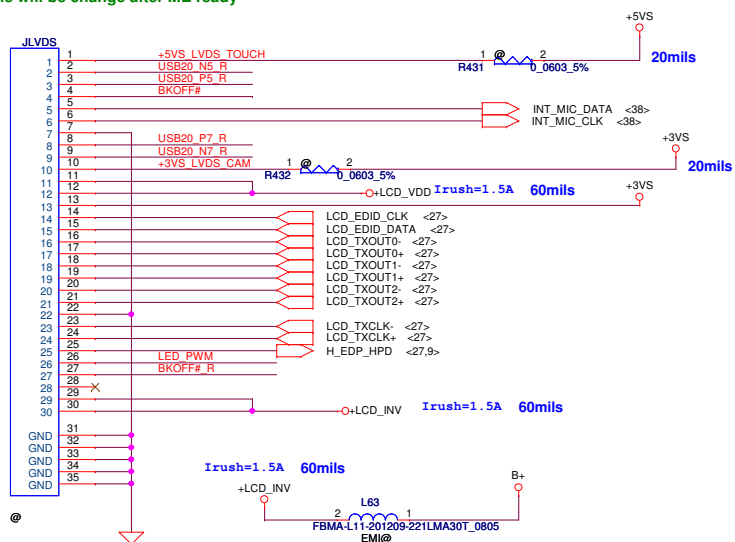


EMI request - Close to JEDP connector

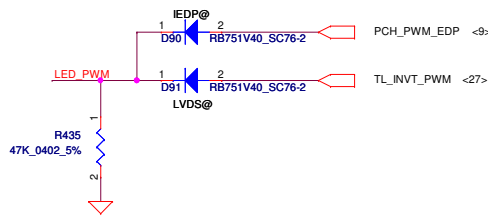
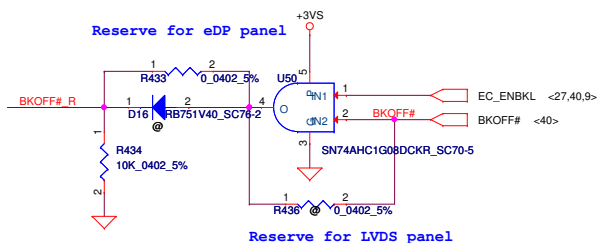
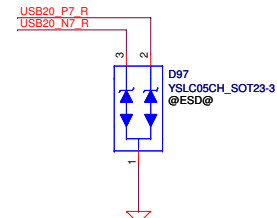
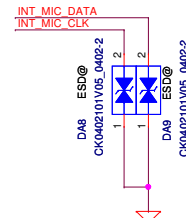
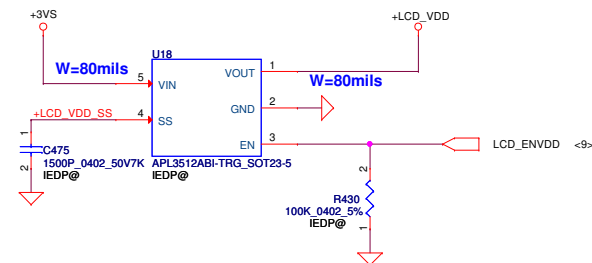


LVDS colay eDP cable

Pin define will be change after ME ready



LCD POWER CIRCUIT (For EDP panel only)



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				Document Number		Rev	
				Custom		VSKTA	
				Date:		Friday, June 21, 2013	
				Sheet		28 of 57	

I2C Mode HDMI ID Setting

If PS8401 use I2C Mode , EQ=I2C_ADDR0 , CFG = I2C_ADDR1

For PS8401
I2C control bus address LSB; Internal pull down at 150kohz±20%, 3.3V I/O.
[I2C_ADDR1, I2C_ADDR0] ; I2C Address (W/R)=
LL: 0x4C/4D (default)
LH: 0x5C/5D
HL: 0xCC/CD
HH: 0xEC/ED

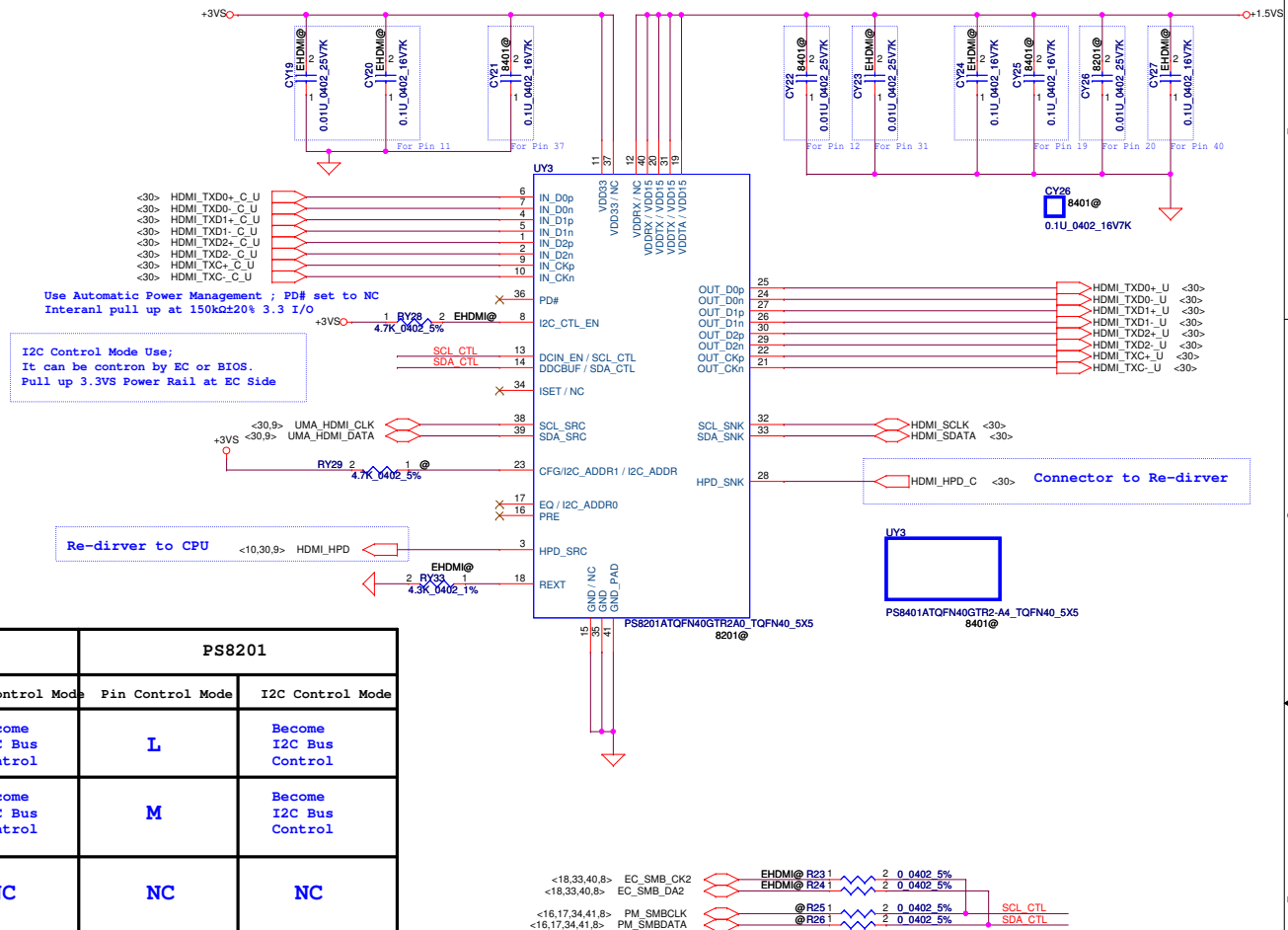
If PS8401 use I2C Mode , EQ=I2C_ADDR

For PS8201
I2C control bus address LSB; Internal pull down at ~150k ohz, 3.3V I/O.
[I2C_ADDR] ; I2C Address (W/R)=
L: 0x64/65 (default)
H: 0xE4/E5

Strap H:3.3V M:1.65V L:0V

Net name	Description	PS8401		PS8201	
		Pin Control Mode	I2C Control Mode	Pin Control Mode	I2C Control Mode
DCIN_EN	DC coupling enable; Internal pull down at 150k ohz ±20%, 3.3V I/O. L: Default, AC coupling input H: DC coupling input	L	Become I2C Bus Control	L	Become I2C Bus Control
DDCBUF	Enable active DDC buffer; Internal pull down at 150k±20%, 3.3V I/O. L: default, passive DDC pass-through H: active DDC buffer with default threshold M: active DDC buffer without internal pull up resistor	M	Become I2C Bus Control	M	Become I2C Bus Control
ISSET	TMDS output swing adjustment; Internal pull down at 150k±20%, 3.3V I/O. For PS8401 Only ISET = L: Default H: Increase +13% M: Reduce -13%	L	NC	NC	NC
CFG	CFG: Configuration pin, 3.3V IO, internal pull down at 150k±20%. 3.3V I/O CFG = L: HDMI ID disable H: HDMI ID enable	H	NC	H	NC
EQ	EQ:Receiver equalization setting; Internal pull down at ~150k?, 3.3V I/O For PS801 EQ = L:programmable EQ for channel loss up to 6.5dB @ 3.0Gbps H:programmable EQ for channel loss up to 9.5dB @ 3.0Gbps M:programmable EQ for channel loss up to 3dB @ 3.0Gbps For PS8401 EQ = L:programmable EQ for channel loss up to 12.4dB H:programmable EQ for channel loss up to 4.3dB M:programmable EQ for channel loss up to 8.6dB	M	NC	M	NC
PRE	Output pre-emphasis setting; Internal pull down at 150k±20%, 3.3V I/O. PRE = L: No pre-emphasis H: 1.6dB pre-emphasis M: 2.5dB pre-emphasis	L	NC	L	NC
I2C_CTL_EN	I2C Control enable. Internal pull down at 150k±20%. 3.3V I/O I2C_CTL_EN = LOW (L): Pin Control is selected. HIGH (H): I2C Control is selected.	L	H	L	H

Note: PS8401 have Jitter cleaning function and can control TMDS output swing , PS8201 don't have.



Vinafix

HDMI TMSD BUS

Componet close to Conn.
Impedance depend on platform design guide

HDMI POWER CIRCUIT
VIN = 5V, IOUT = 0.5A, RDS(ON) TYP=95m ; MAX=115m
Current Limit: TYP=0.8A ; MAX=1A

HDMI Connector

Security Classification

Security Classification	Compal Secret Data
Issued Date	2012/10/19
Deciphered Date	2015/10/19

Compal Electronics, Inc.

HDMI Conn.

VSKTA

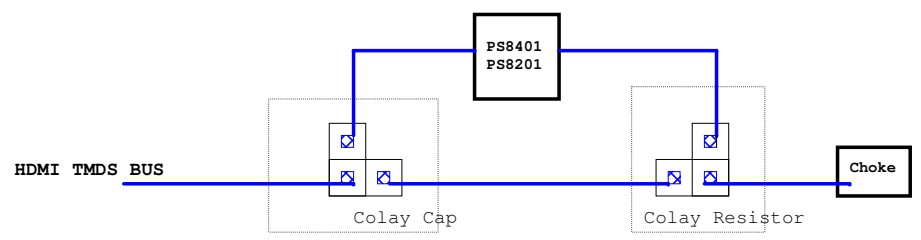
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Document Number: VSKTA

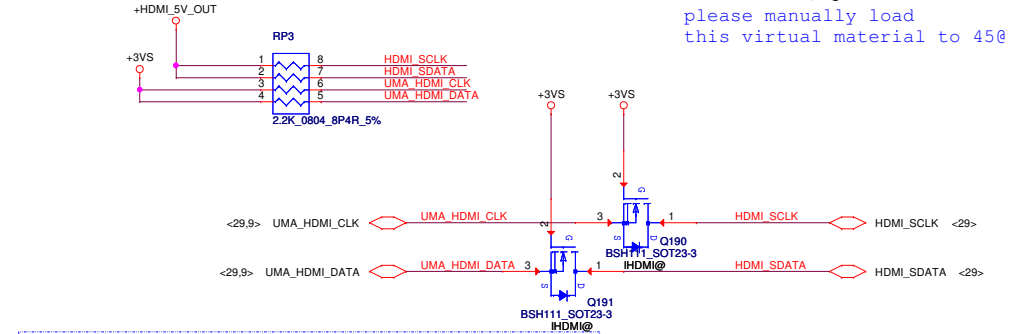
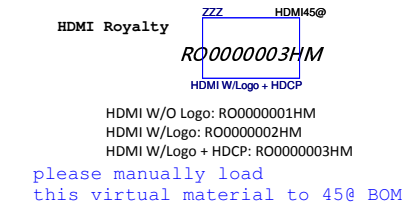
Date: Friday, June 21, 2013

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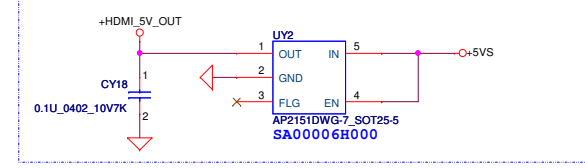


Componet close to Conn.
Impedance depend on platform design guide

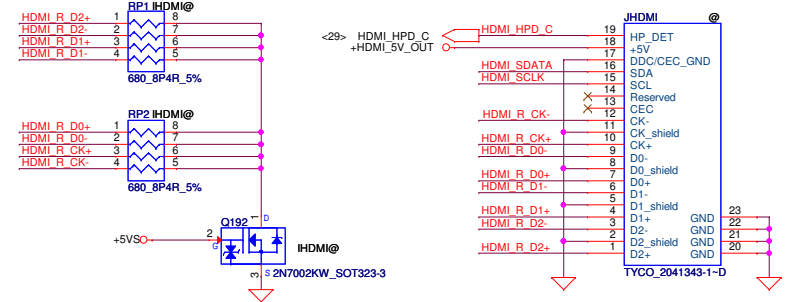


HDMI POWER CIRCUIT

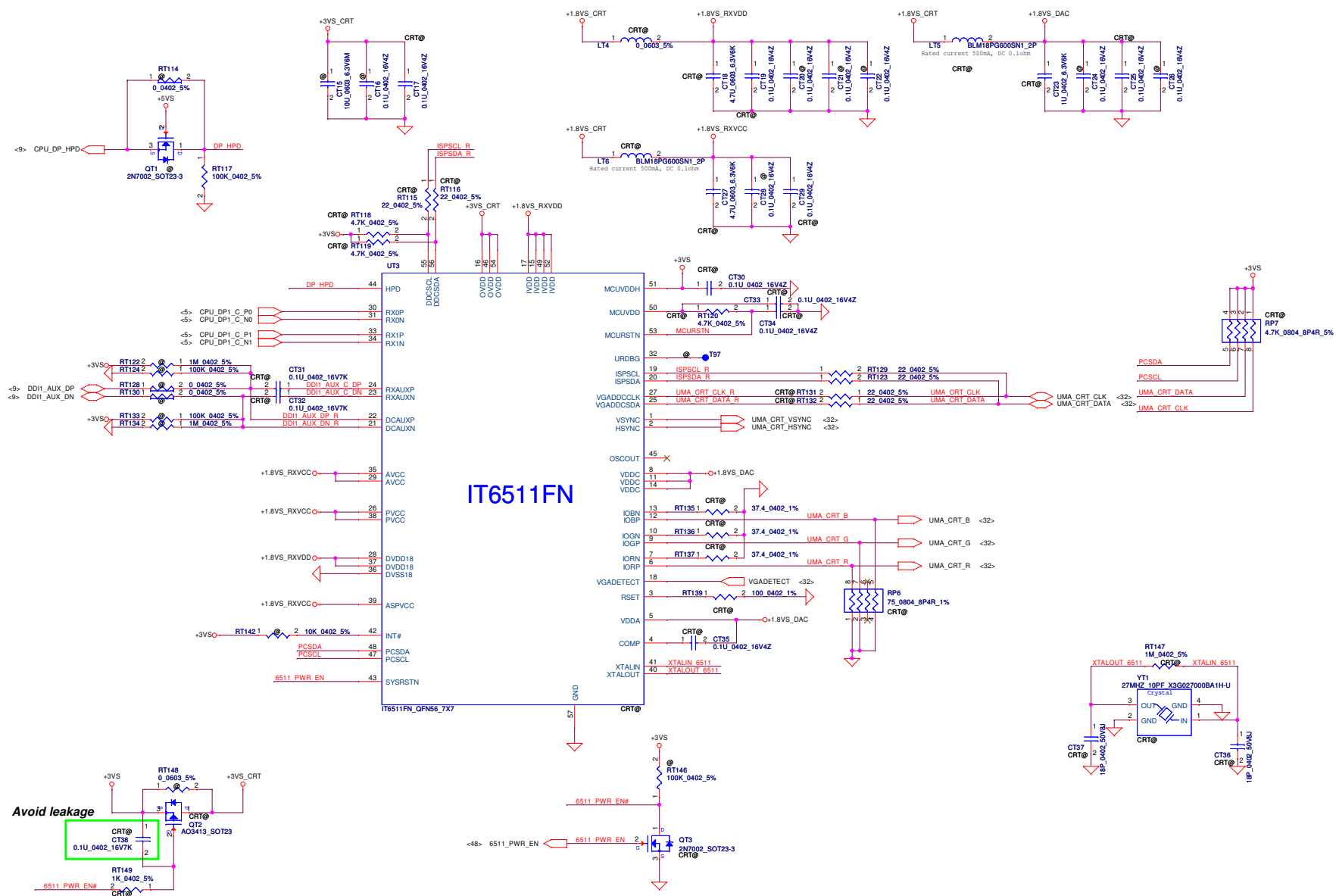
VIN = 5V, IOUT = 0.5A , RDS(ON) TYP=95m ; MAX=115m
Current Limit: TYP=0.8A ; MAX=1A

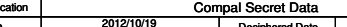


HDMI Connector

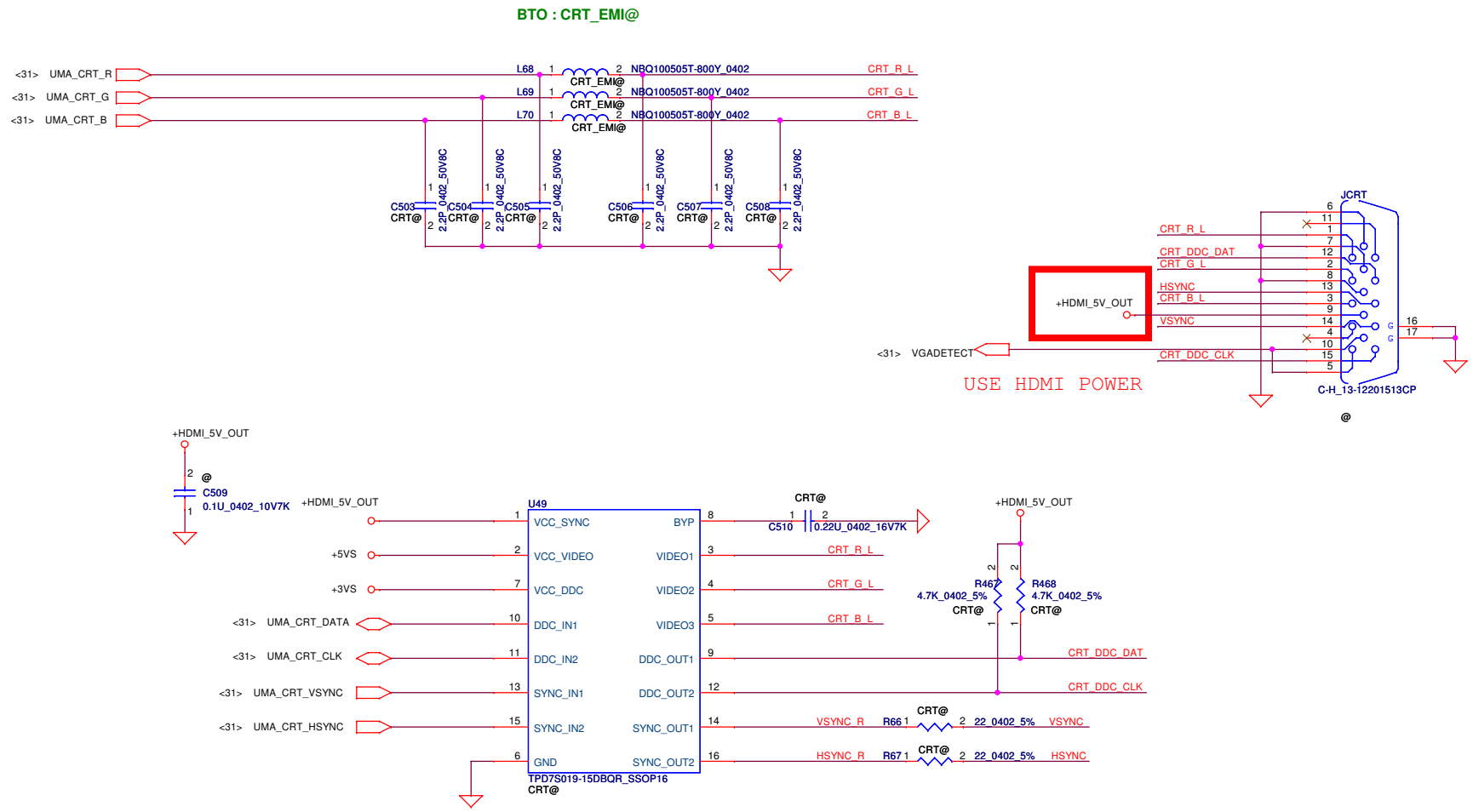


Security Classification		Compal Secret Data		Compal Electronics, Inc.		
Issued Date	2012/10/19	Deciphered Date	2015/10/19	Title	HDMI Conn.	
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				Date:	Friday, June 21, 2013	Rev 2.0
C		D		Sheet 30 of 57		



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			DP-CRT ITE IT6511FN	
			DP to VGA	
Date: Friday, June 21, 2013			Sheet	51 of 57

CRT CONNECTOR



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Issued Date		2012/10/19		Deciphered Date		2015/10/19		Title	
								CRT	
								Size	
								Document Number	
								VSKTA	
								Rev	
								2.0	
								Date:	
								Friday, June 21, 2013	
								Sheet	
								32 of 57	

Left USB 2.0 x 1

DLW21HN900SQ2L_4P

LR5 EMI@

USB20_P2

USB20_N2

USB20_P2_L

USB20_N2_L

2.0A

U13

GS472P81U_MSP08
SA00003TV00
SA00003XM00

+5VALW

+USB_VCC

W=80mils

USB_EN#2

USB_OC#2

<10,11,40>

For LAN function

3V3

RL24 2 1 10K 0402 5% LANCLK_REQ#

<10,8> LAN_EN

<8> CLKREQ_LAN#

QL53

2N7002KW_SOT323-3

LANCLK_REQ#

3V3

1K 0402 5% RL6

ISOLATE# RL433 1 2 0 0402 5%

WOL_EN# <40>

	Sx Enable Wake up	Sx Disable Wake up
WOL_EN#	LOW	HIGH



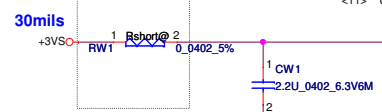
+3V_LAN rising time (10%~90%) need > 1ms and <100ms.

LAN	WOL	LAN_EN		ISOLATEB	
		S0	Sx	S0	Sx
0	0	0	0	1	1
0	1	0	0	1	1
1	0	1	1	1	1
1	1	1	1	1	0*

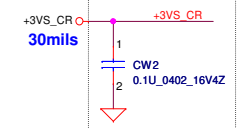
```
*
S3:  after SUSP# assert low over 100ms
S4/S5: after SYSON assert low over 100ms
```

Security Classification	Compal Secret Data			Compal Electronics, Inc. PCIe-LAN-RTL8111G-CG/LUSB		
Issued Date	2012/10/19	Deciphered Date	2015/10/19	Title		
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				Date:	Friday, June 21, 2013	Sheet 35 of 57

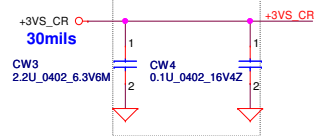
For power consumption measurement and remove it after Pre-MP phase



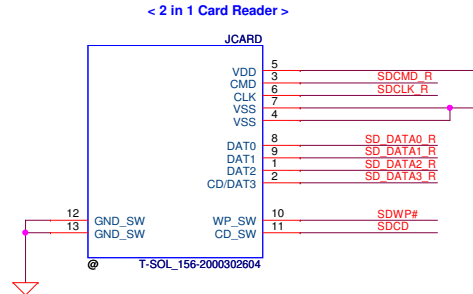
please close the pin19 of UW1



please close the pin4 of UW1



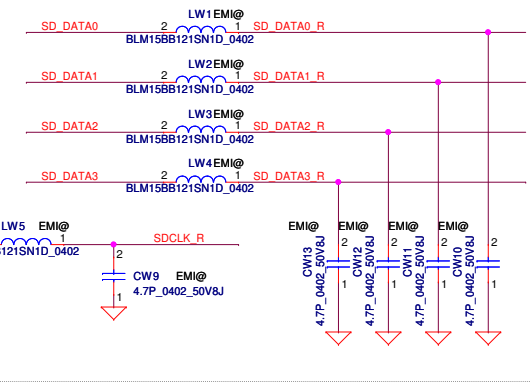
De-coupling and Bulk capacitor should place near to Cardreader chip and Combo Socket



"Normal Close" type connector

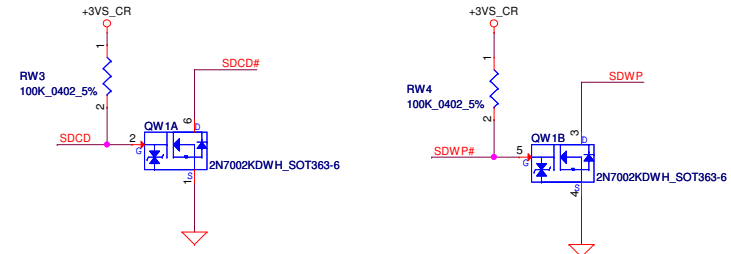
	CD_SW	WP_SW	
Card Uninsertion	Close	Protect disable	Protect Enable
		Close	Close
Card Insertion	Open	Open	Close

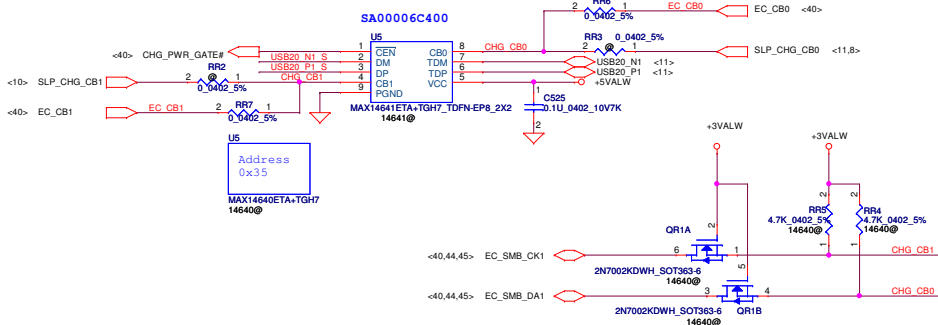
For EMI request
(Place close to chip)



NC (default)	10K pull down
GPI00 Power saving mode	Normal mode

For normal close type connector invert circuit



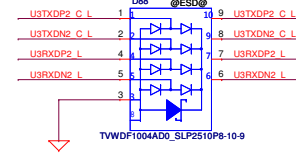
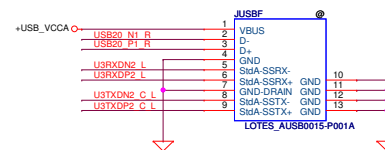
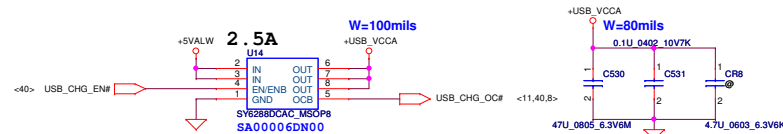
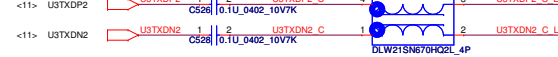
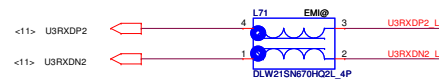
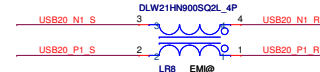
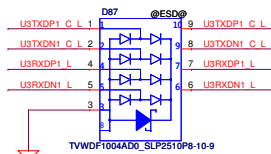
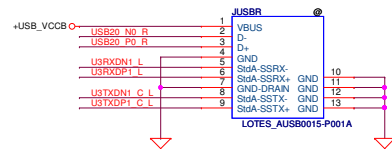
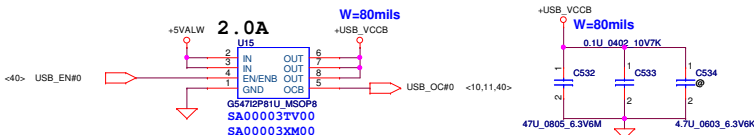
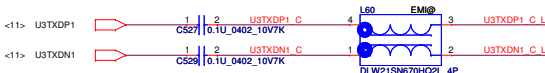
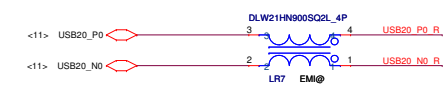


Right rear USB3.0 Conn.

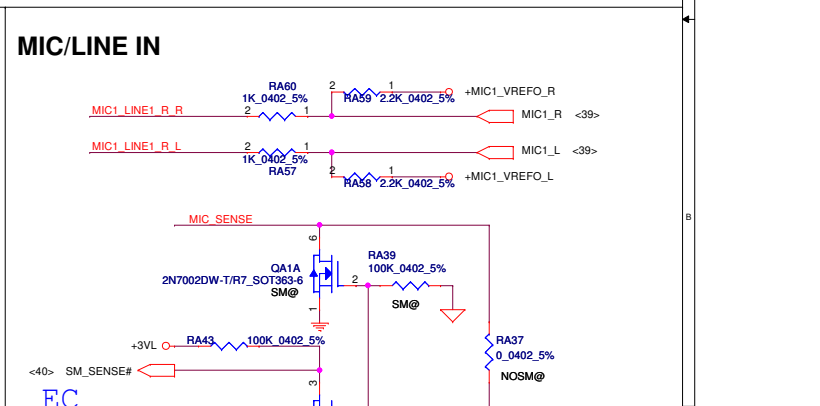
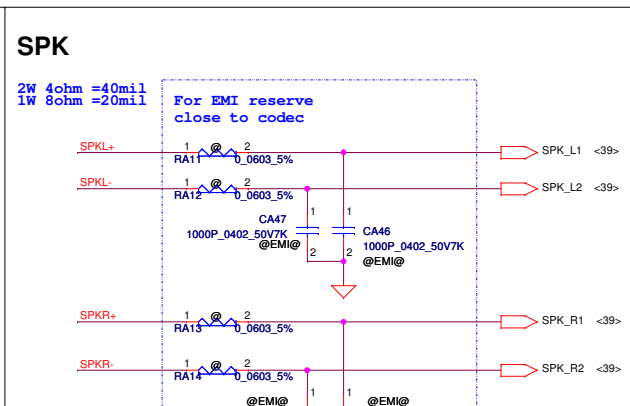
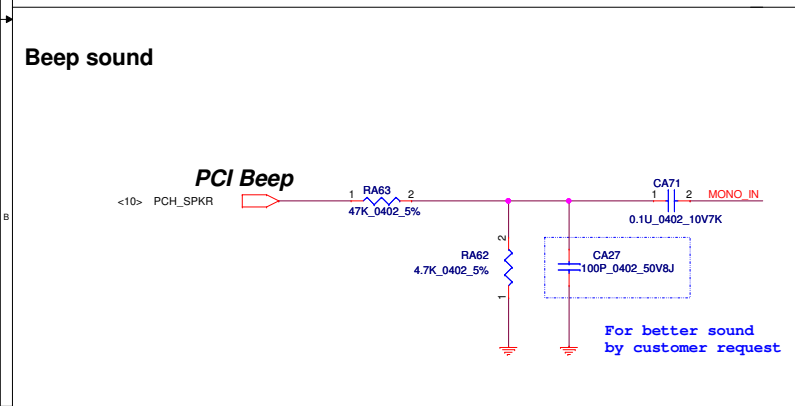
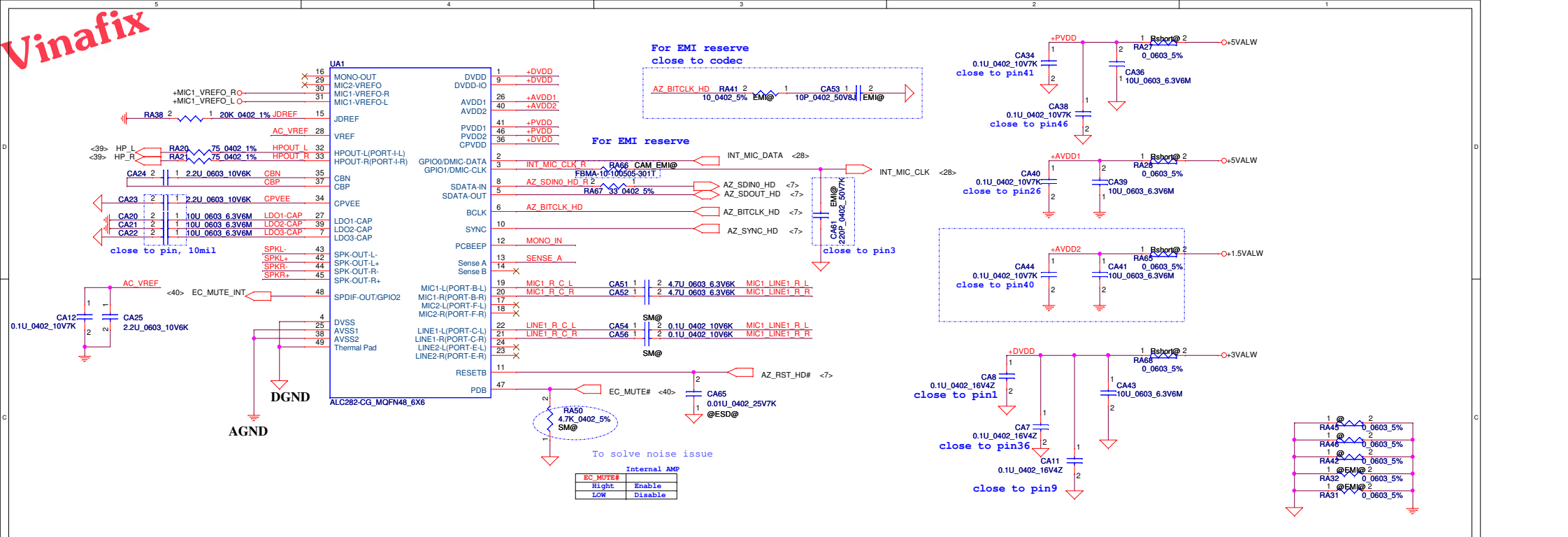
Right front USB3.0 Conn.
(Support S&C function)

USB Sleep & Charge

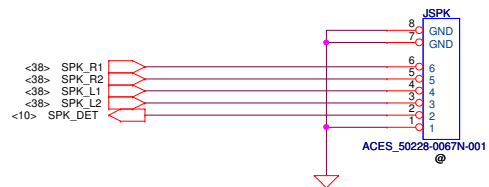
State table for MAX14641			
CB0	CB1	Mode	STATUS
0	0	AM2	2A auto-detection charger mode for Apple device. Resistor dividers are connected to DP/DM, including DCP
0	1	AP1	Forced 1A charger mode for Apple devices. Resistor dividers are connected to DP/DM.
1	0	PM	USB pass-through mode. DP/DM are connected to TDP/TDM
1	1	CM	USB pass-through mode with CDP emulation. Auto connects DP/DM to TDP/TDM depending on CDP detection status.



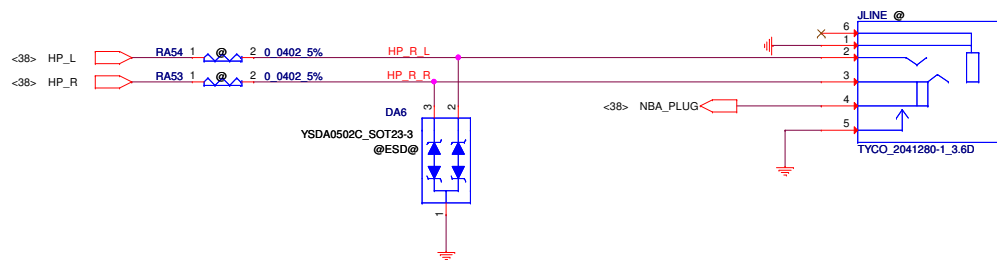
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Size	Document Number	VSKTA		Rev	2.0
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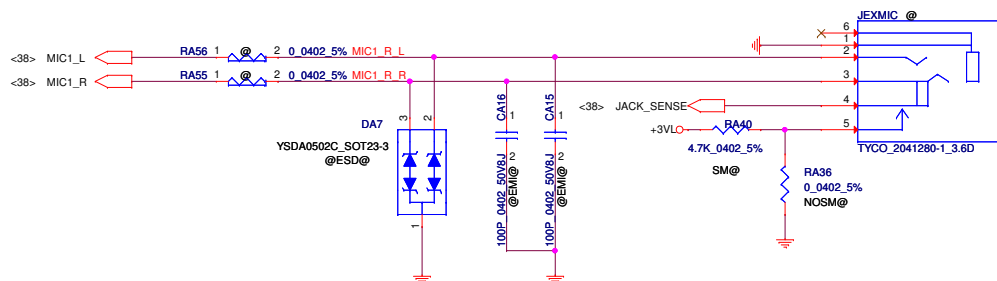
Sense Pin	Impedance	Codec Signals	Function
SENSE A	39.2K	PORT-I (PIN 32, 33)	Headphone out
	20K	PORT-B (PIN 21, 22)	Ext. MIC
	10K	PORT-C (PIN 23, 24)	
	5.1K	(PIN 48)	
SENSE B	39.2K	PORT-E (PIN 14, 15)	
	20K	PORT-F (PIN 16, 17)	
	10K	PORT-H (PIN 20)	



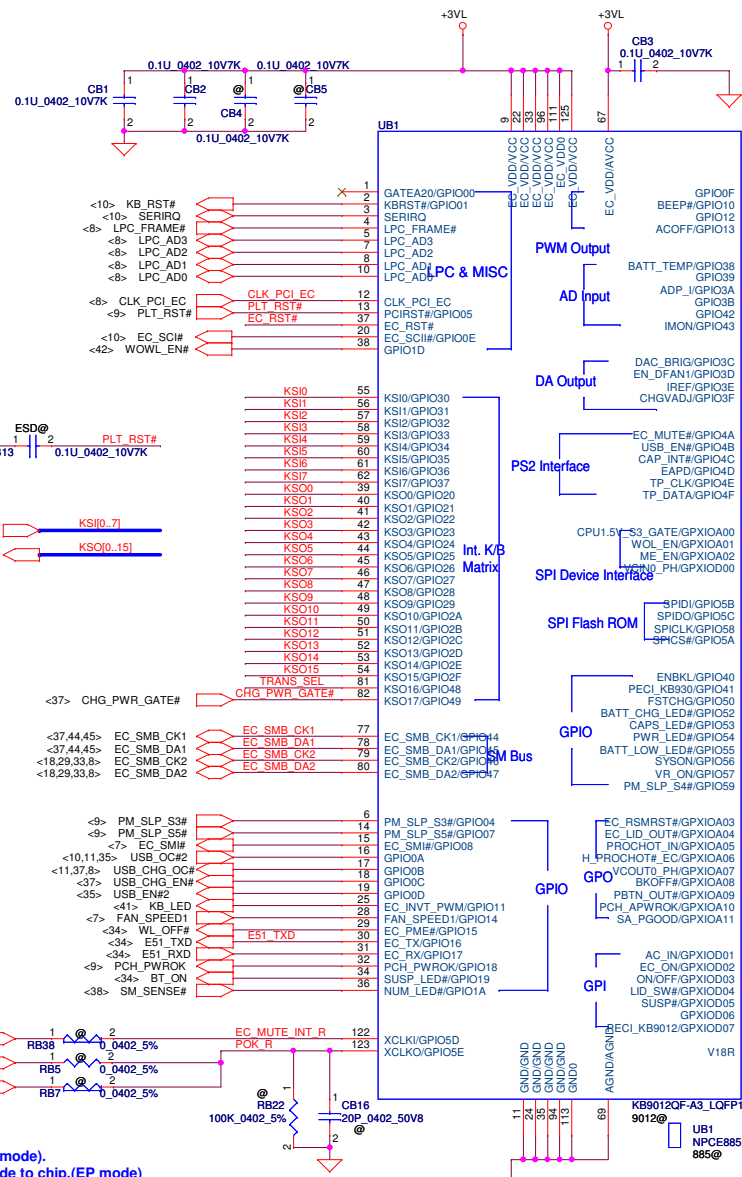
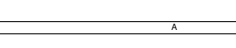
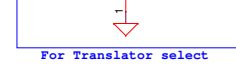
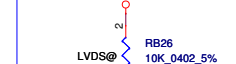
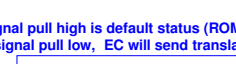
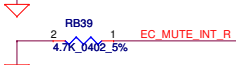
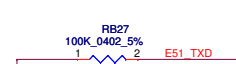
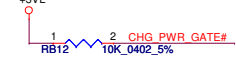
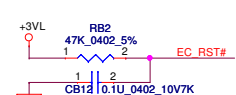
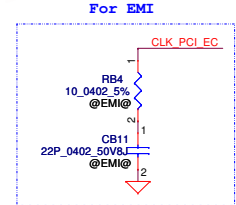
HeadPhone/LINE Out JACK



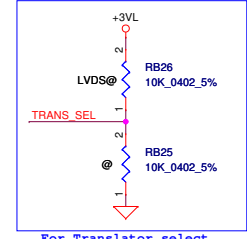
MIC/LINE IN JACK



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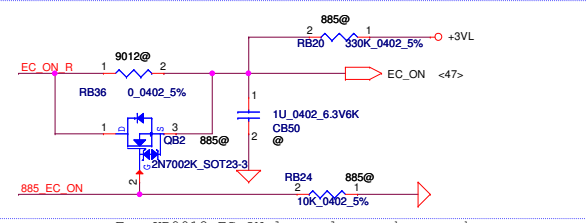
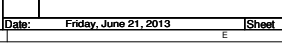
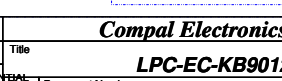
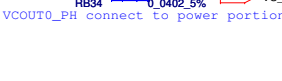
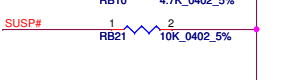
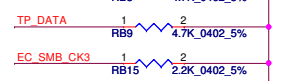
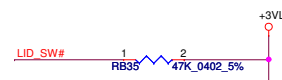
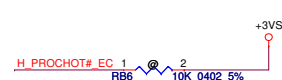
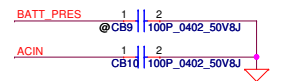
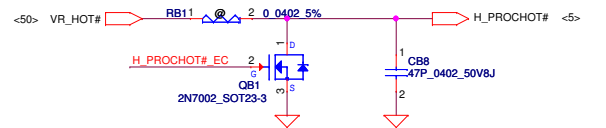
Signal pull high is default status (ROM only mode).
If signal pull low, EC will send translator code to chip.(EP mode)



Voltage Comparator Pins FOR 9012 A3

VCIN0 pin109	>1.2V	<1.2V
VCIN1 pin102	HIGH	LOW
VCOUT0 pin104	HIGH	LOW
VCOUT1 pin105	HIGH	LOW

<http://www.vinafix.vn>

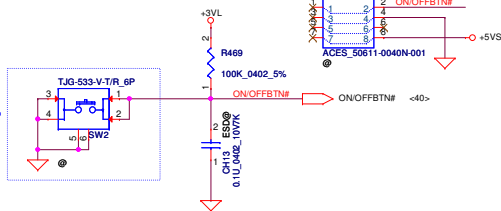


For KB9012 EC_ON low pulse work around

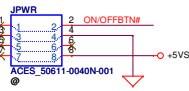
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Issued Date	2012/10/19	Deciphered Date	2015/10/19	Title	
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Date: Friday, June 21, 2013		Sheet 40 of 57		LPC-EC-KB9012&930	

Power Button

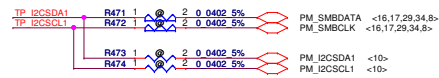
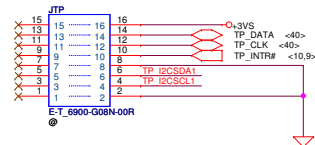
Place on BOT
Debug used
@ after PVT



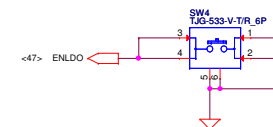
Conn.



Touchpad Connector

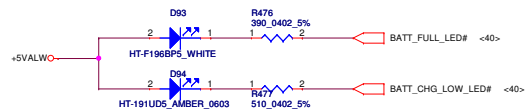


Battery Reset



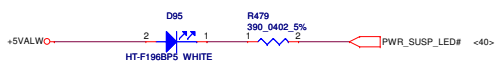
LED/LID

BATT CHARGE /FULL LED



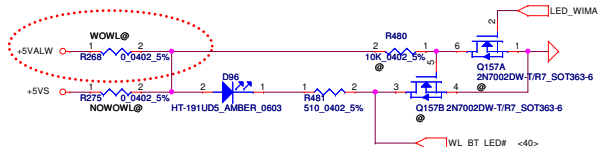
White LED bright when both AC-adaptor is plugged in and Battery is full charged
Amber LED bright while charging battery from AC-adaptor.
Amber LED blink during Critical Low Battery

POWER LED



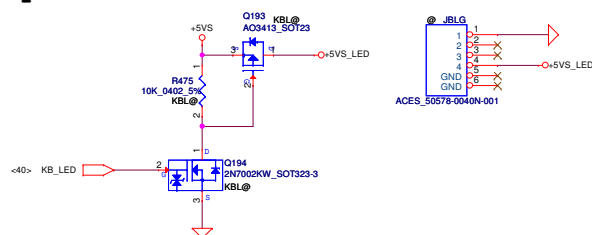
White LED bright when system is power on.
White LED blink when system is sleep mode.

WLAN/WiMAX LED

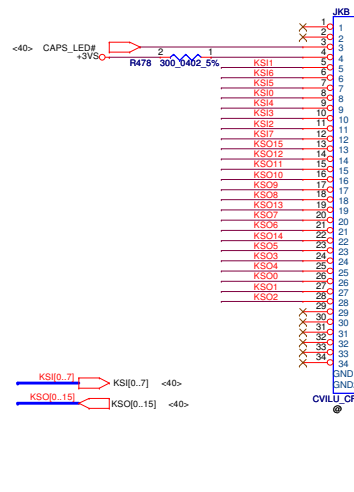


Amber LED bright while Wireless and/or WiMAX turns on.

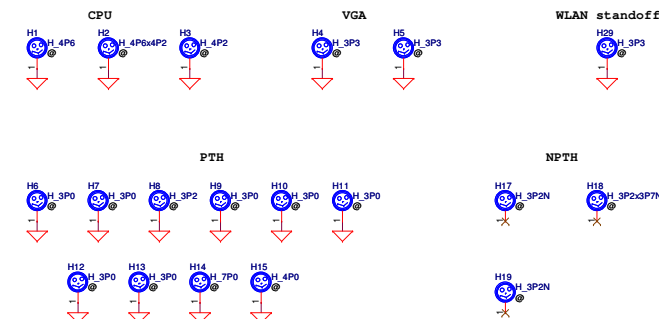
Keyboard LED



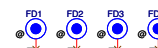
NEW KEYBOARD CONN.



Screw Hole



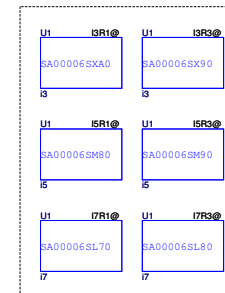
PCB Federal Mark PAD



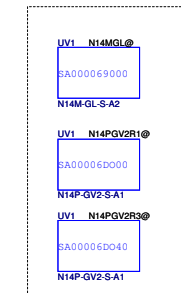
ISPD



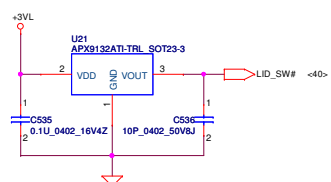
CPU

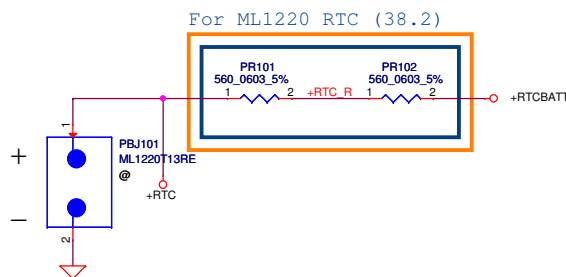
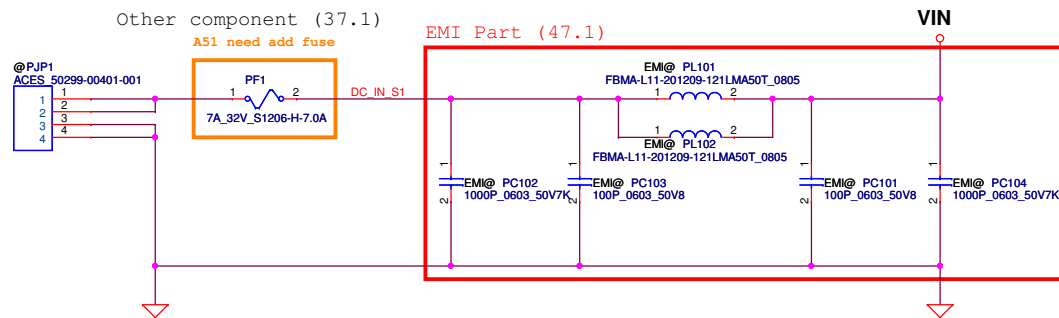


GPU

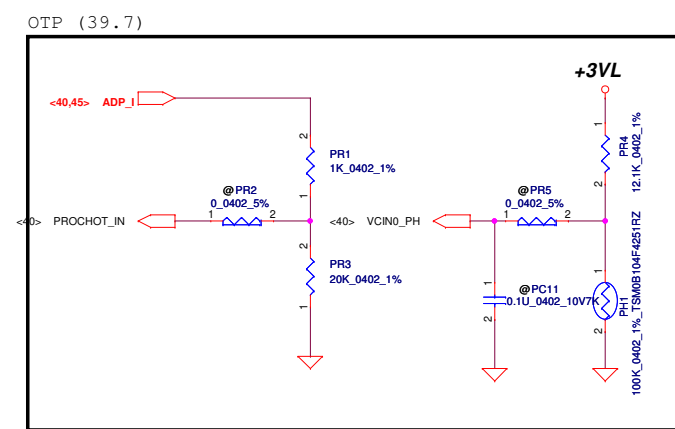
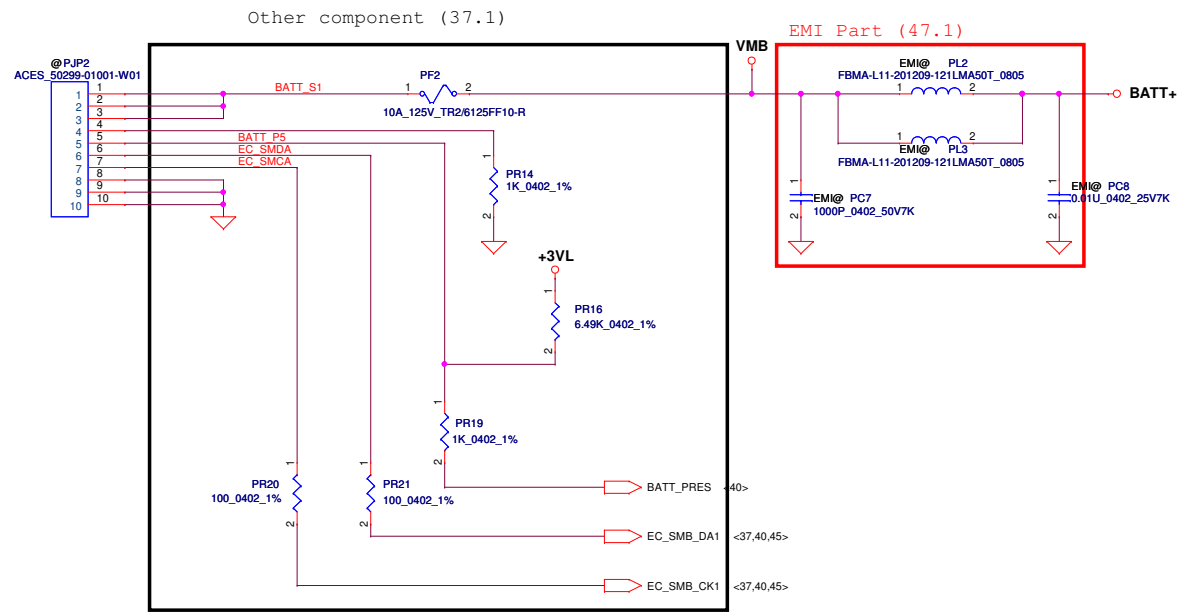


Lid SW





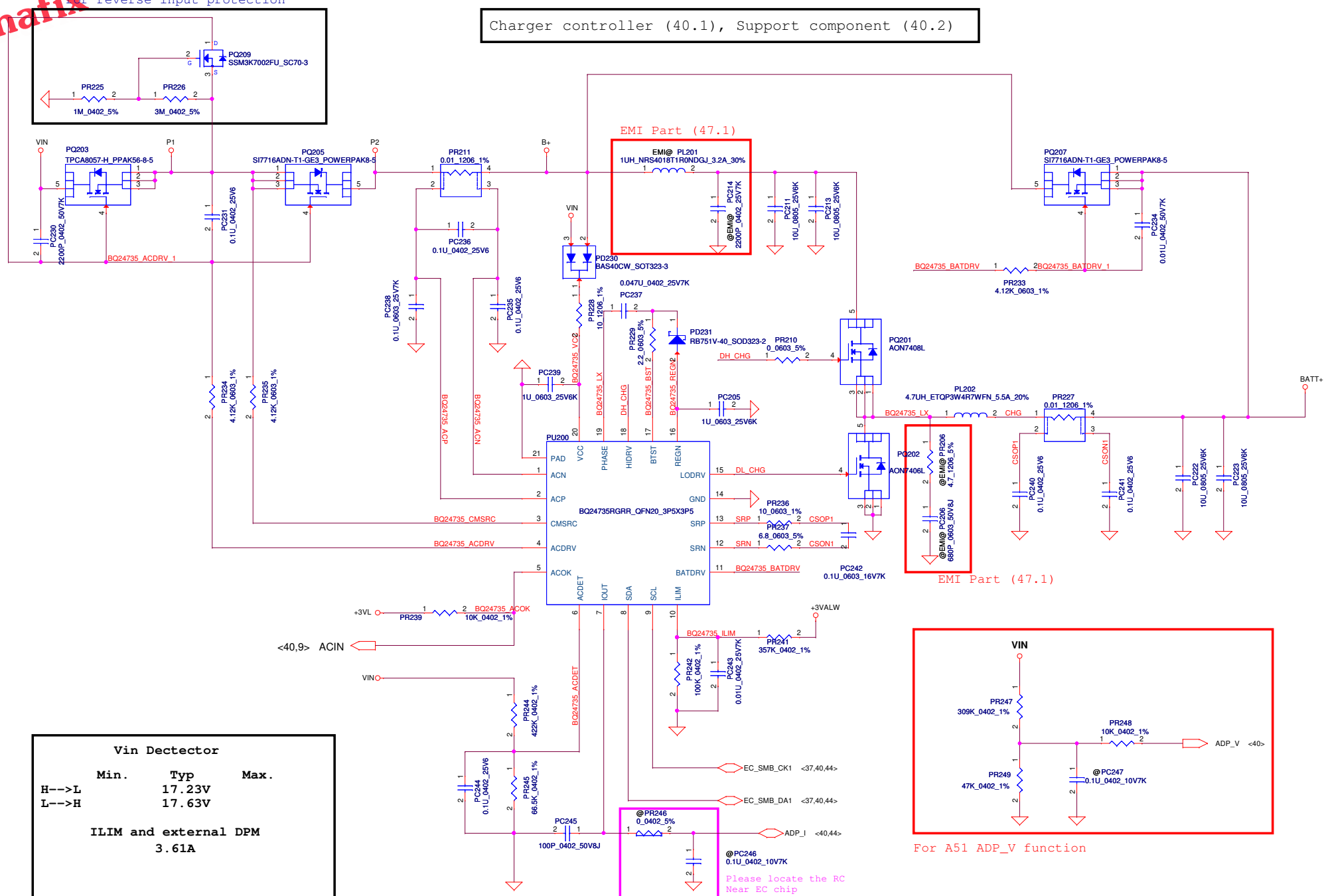
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Issued Date		Deciphered Date	Title DCIN	
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Date:		Sheet 43 of 57		

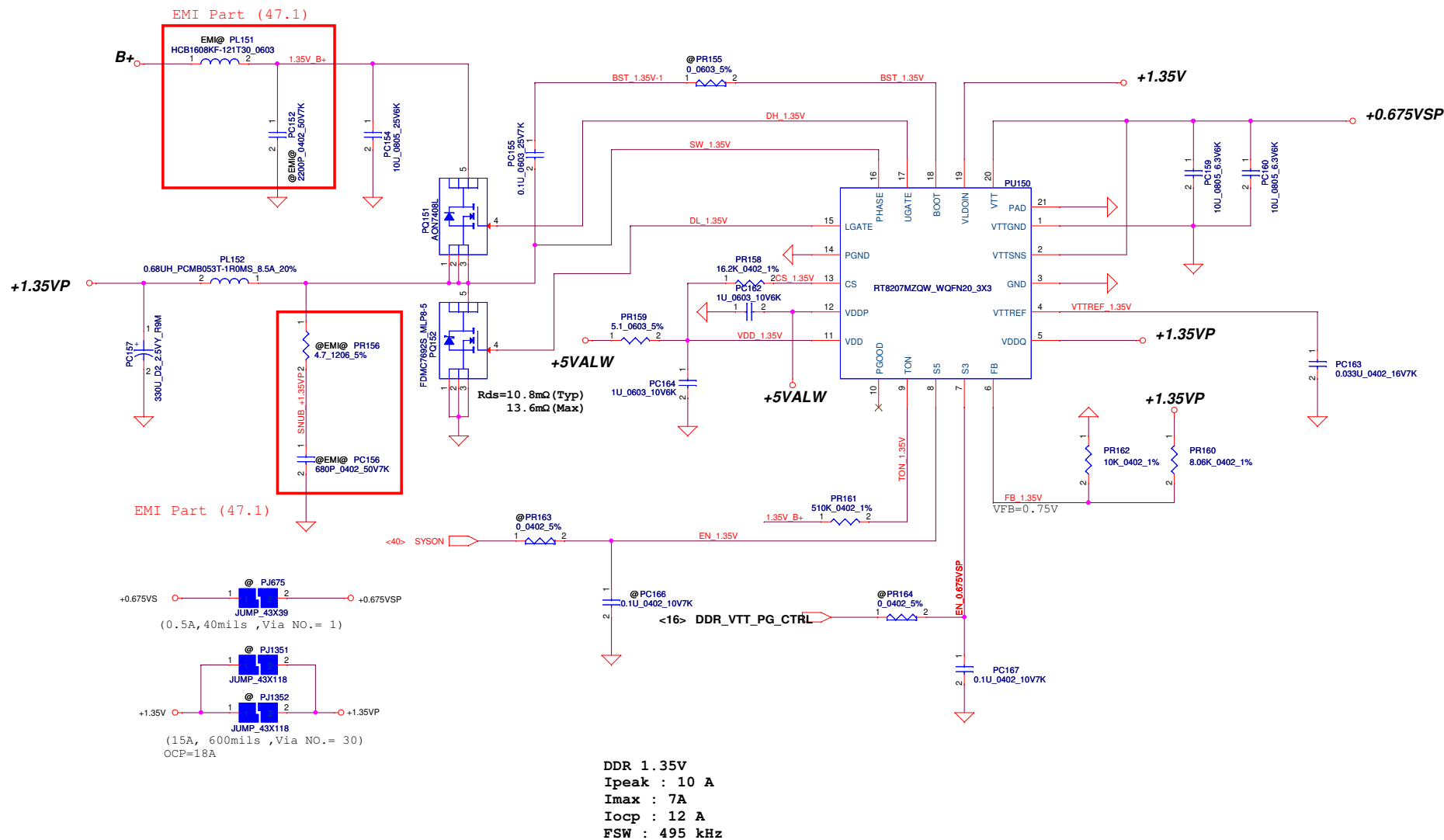


	Initial	Recovery
45W Int GPU	0.55V	0.43V
75W N14P-GV2	0.90V	0.72V

	Initial	Recovery
CPU OTP	90 C	70 C

Charger controller (40.1), Support component (40.2)

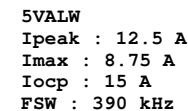




STATE	S3	S5	1.5VP	VTT_REFP	0.75VSP
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off (Discharge)	Off (Discharge)	Off (Discharge)

Note: S3 - sleep ; S5 - power off

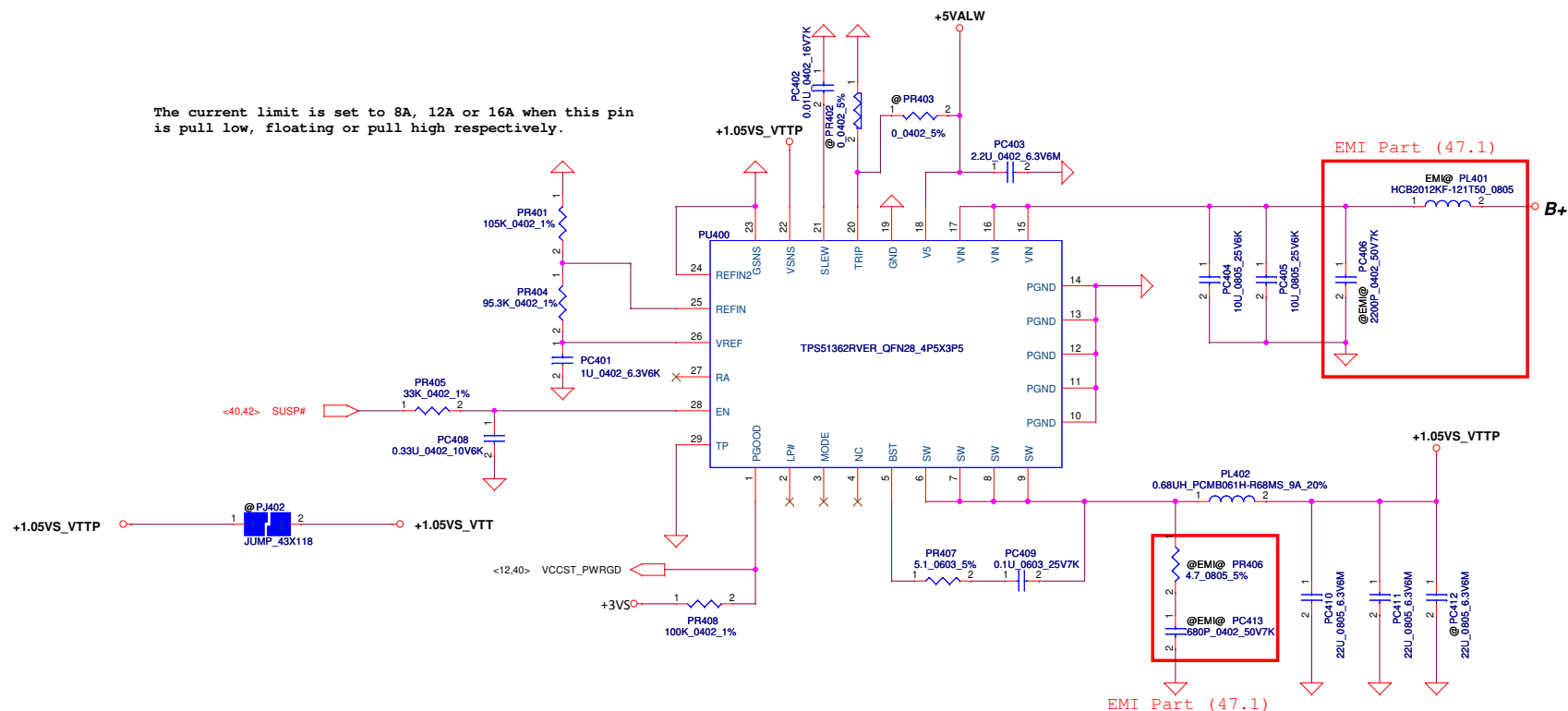
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				1.35VP/0.675VSP			
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				Custom		2.0	
				VSKTA			
				Date:		Sheet 46 of 57	



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					VSKTA	2.0
Date:				Sheet	47	of 57

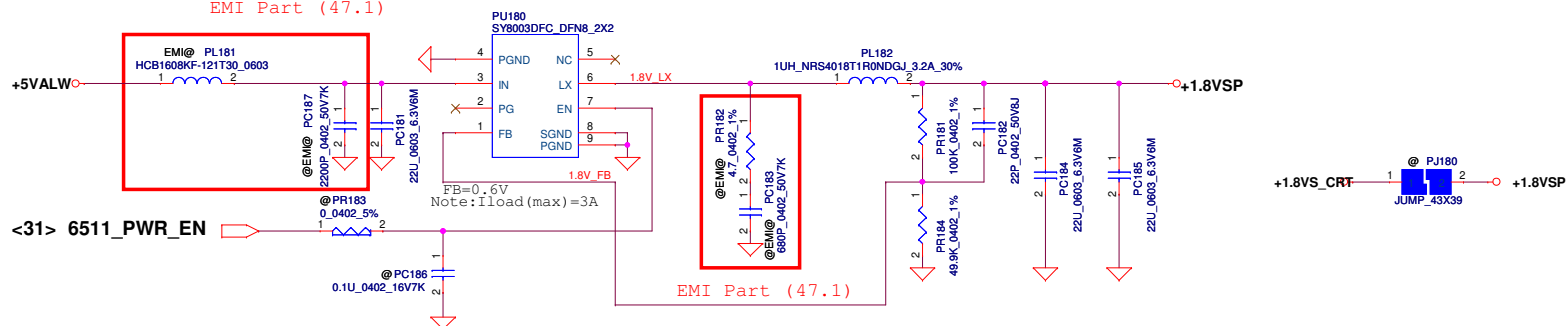
1.05VCCP controller (35.5), Support component (35.6)

The current limit is set to 8A, 12A or 16A when this pin is pull low, floating or pull high respectively.

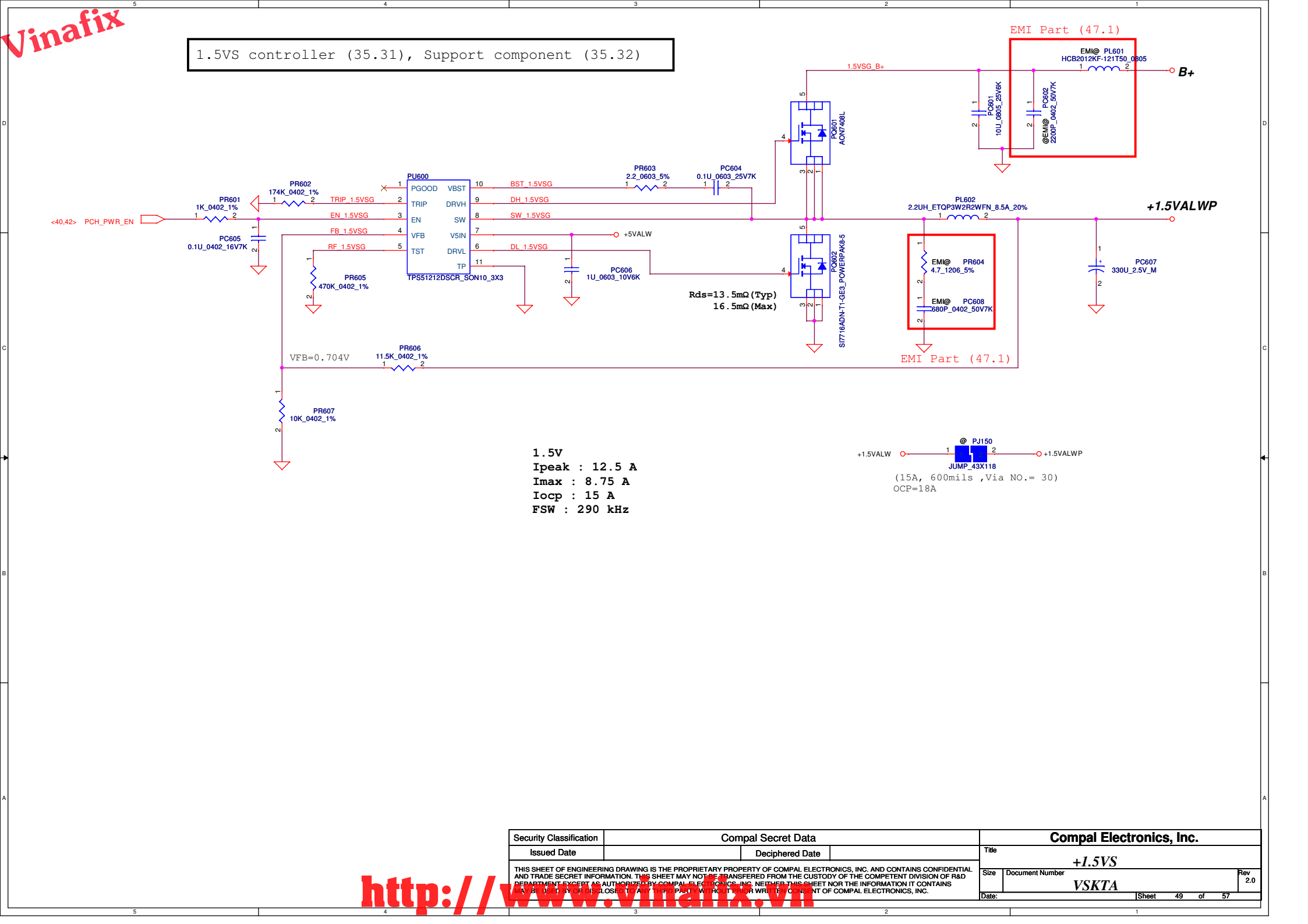


1.8VS controller (35.15), Support component (35.16)

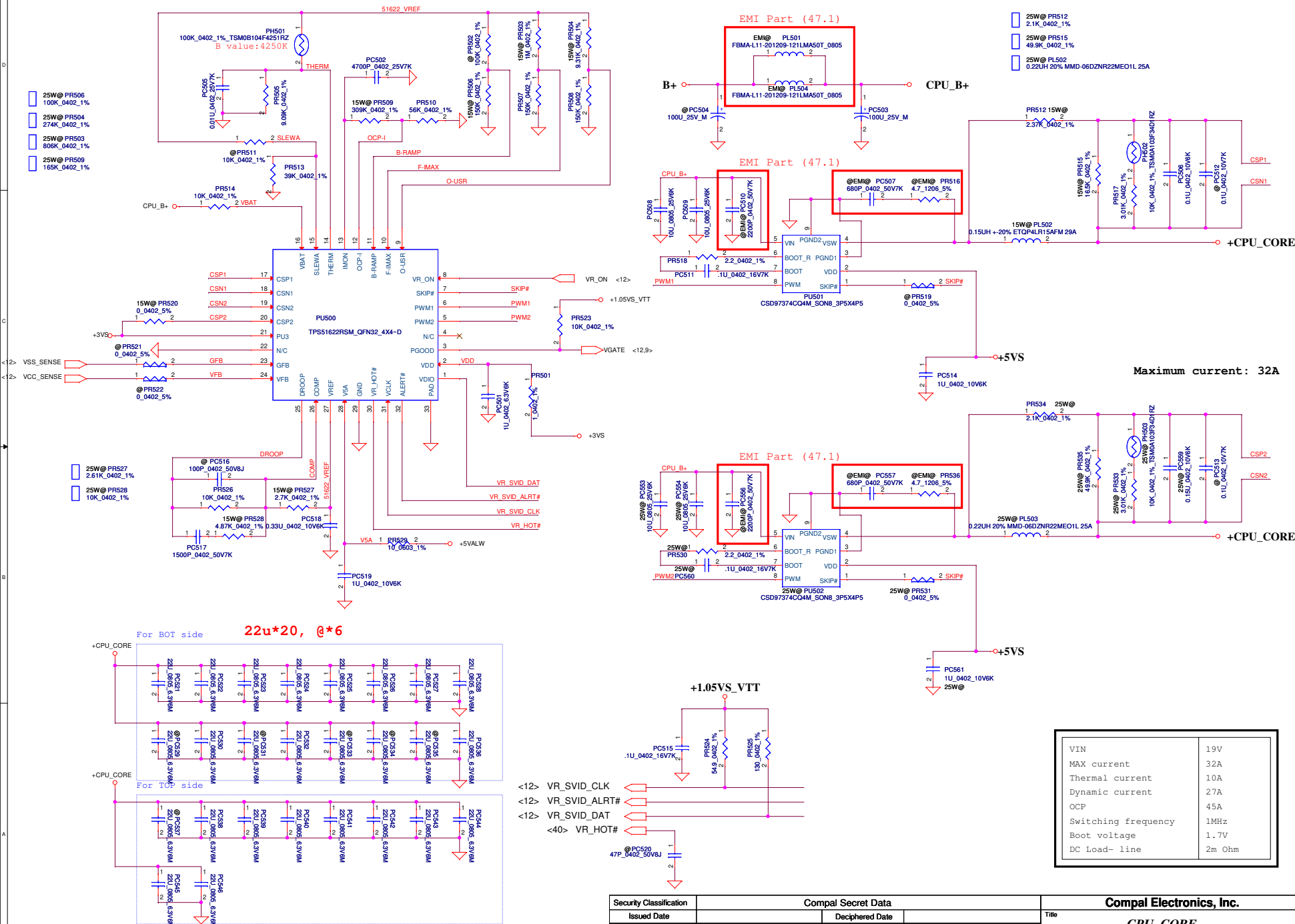
EMI Part (47.1)



Security Classification		Compal Secret Data		Compal Electronics, Inc.		
Issued Date		Deciphered Date		Title	+1.05VS_VCCP/1.8VSP	
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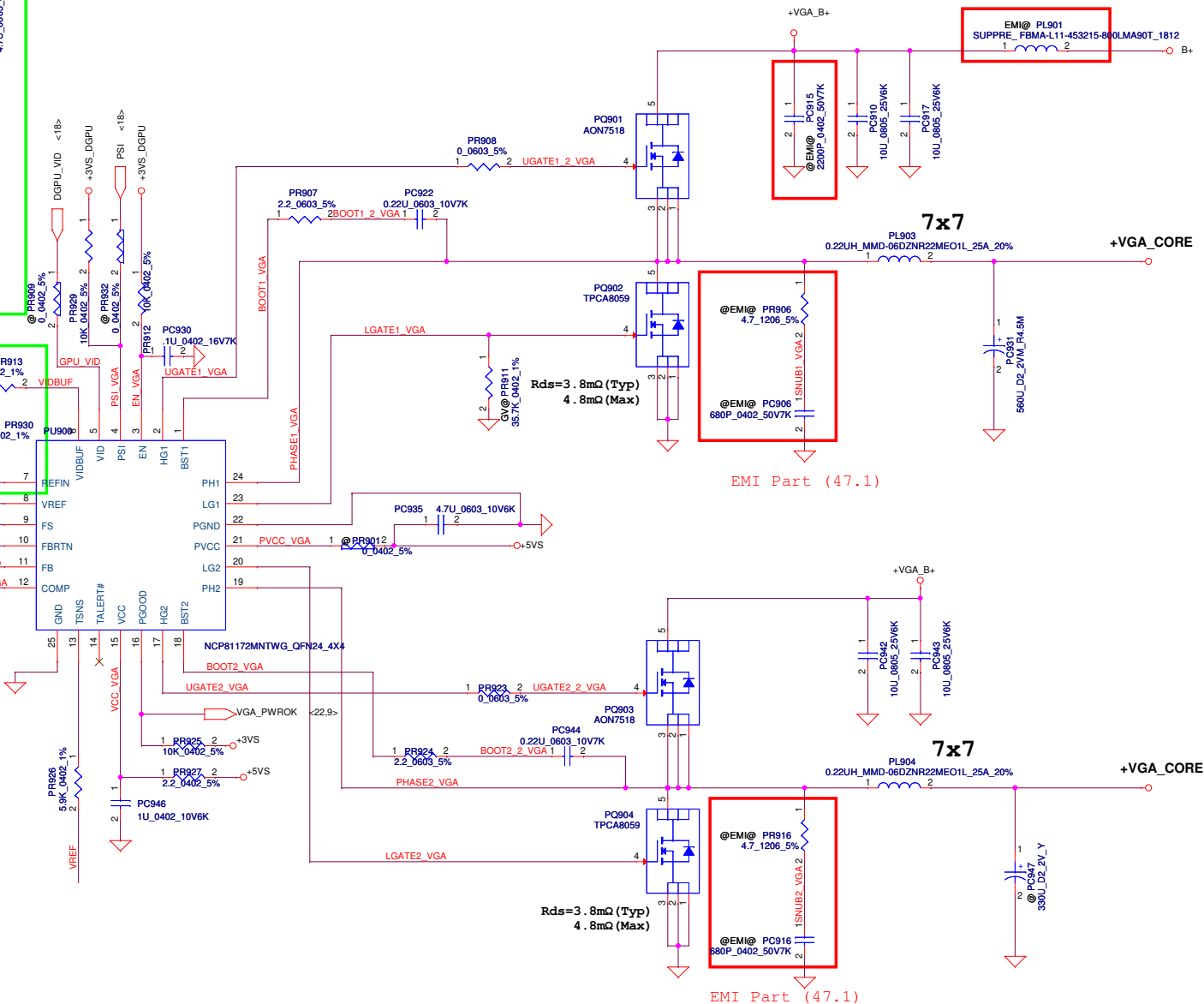
+VCC_CORE controller (36.1), Support component (36.3)
driver(36.2), decoupling cap(36.4)



GB4-128 package



EMI Part (47.1)



	N14P-GV2	N14M-GL
R1 PR913	20 Kohm	39 Kohm
R2 PR915	20 Kohm	30 Kohm
R3 PR930	2 Kohm	3 Kohm
R4 PR914	18 Kohm	27 Kohm
C PC940	2.7 nF	1.8 nF

- ☐ GL@ PR913
39K_0402_1%
- ☐ GL@ PR915
30K_0402_1%
- ☐ GL@ PR930
3K_0402_1%
- ☐ GL@ PR914
27K_0402_1%
- ☐ GL@ PC940
1800P 0402 50V7K

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				Date		Sheet	51 of 57
				VSKTA			

fix					fix									
Vi					fix									
P W R P I R (Product Improve Record)														
VSKTA LA-9865P Schematic Change List														
Item	Time (When)	Page (Where)	Location / Discription (How / What)	Request (Who)	Reson (Why)									
1	EVT--2012/11/28		Add / PC101, PC103, PC102, PC104, PC7, PC8, PL151, PC181, PL2, PC3, PL101, PL102, PL331, PL401, PL601, PL501, PL901	EM I	EM I request									
2	EVT--2012/11/28	P50-PW R-CPU_CORE	Value change / PR529, PR520, PR528, PR503, PR507, PR515, PR527, PR509, PR510, PR504, PC516, PL502, PC543, PC544, PC545, PC546, PC514, PC519	PW R	TPS51622 for 15W CPU setting									
3	EVT--2012/11/28	P48-PW R-1.05VS_VCCP/1.8VSP	Value change / PR407, PR401, PR404, PR405, PC404, PC405	PW R	For TPS51362 design change									
4	EVT--2012/11/28	P46-PW R-1.35VP/0.675VSP	Short pad reserve / PR163	PW R										
5	EVT--2012/11/28	P47-PW R-3VALW /5VALW	PC351 reserve / PC352 mount	PW R	M E lim itation									
6	EVT--2012/11/28	P50-PW R-CPU_CORE	PC504 reserve	PW R	M E lim itation									
7	EVT--2012/11/28	P44-PW R-BATTERY CONN / OTP	PF2 change vendor	PW R	for com m on design change									
8	EVT--2012/11/29	P46-PW R-1.35VP/0.675VSP	change m aterial / PL152	PW R	for com m on design change									
9	DVT-2012/12/13	P43-PW R-DCIN	m odify PBJ101 footprint	PW R	for com m on design change									
10	DVT-2012/12/13	P44-PW R-BATTERY CONN / OTP	m odify PR20, PR21 pin define	PW R	for layout module request									
11	DVT-2012/12/13	P46-PW R-1.35VP/0.675VSP	change PR160 to 8.06K	PW R	for output voltage level									
12	DVT-2012/12/13	P46-PW R-1.35VP/0.675VSP	m odify PL152, PC155, PR164 pin define	PW R	for layout module request									
13	DVT-2012/12/13	P47-PW R-3VALW /5VALW	del PC331, PC351	PW R	M E lim itation									
14	DVT-2012/12/13	P47-PW R-3VALW /5VALW	m odify PL332, PR337, PR342, PR357 pin define	PW R	for layout module request									
15	DVT-2012/12/13	P47-PW R-3VALW /5VALW	m odify the VS_ON direction	PW R	input signal									
16	DVT-2012/12/13	P48-PW R-1.05VS_VCCP/1.8VSP	change the 1.8VSP EN to 6511_PW R_EN	PW R	for High enable									
17	DVT-2012/12/13	P48-PW R-1.05VS_VCCP/1.8VSP	m odify PR401, PC402, PR182 pin define	PW R	for layout module request									
18	DVT-2012/12/13	P49-PW R-1.5VALW P	change PR603 to 0ohm	PW R	VBST resistor									
19	DVT-2012/12/13	P49-PW R-1.5VALW P	m odify PR602, PR606, PL601 pin define	PW R	for layout module request									
20	DVT-2012/12/13	P50-PW R-CPU_CORE	change the B+ EM I bead	PW R	M E lim itation									
21	DVT-2012/12/13	P50-PW R-CPU_CORE	m odify PC516, PR526, PR527, PC517, PR529, PR512, PR516, PR518, PR534, PR536, PR530, PR524 pin define	PW R	for layout module request									
22	DVT-2012/12/13	P51-PW R-VGA_CORE	PR912/add 10K ohm	PW R	pull high +3VS_DGPU									
23	DVT-2012/12/13	P51-PW R-VGA_CORE	PC934 change to 0.01u	PW R	VREF pull down cap									
24	DVT-2012/12/13	P51-PW R-VGA_CORE	m odify PL901, PR908, PR907, PR901, PR923, PR924, PR927, PC946, PR913, PR915, PR914, PR904, PR928, PR931, PR932, PR909 pin define	PW R	for layout module request									
25	PVT-2013/01/25	P47-PW R-3VALW /5VALW	change PC332,PC352,PR409 location to PC331,PC351,PR335	PW R	for com m on design change									
26	PVT-2013/01/25	P46-PW R-1.35VP/0.675VSP	change PL152 value from 1uH to 0.68uH	PW R	for com m on design change									
27	PVT-2013/01/25	P46-PW R-1.35VP/0.675VSP	change PC157 to 390uF 5*5.7	PW R	layout request									
28	PVT-2013/01/25													

Item	Time (When)	Page (Where)	Location / Discription (How / What)	Request (Who)	Reson (Why)
1	EVT--2012/11/28		Add / PC101, PC103, PC102, PC104, PC7, PC8, PL151, PC181, PL2, PC3, PL101, PL102, PL331, PL401, PL601, PL501, PL901	EM I	EM I request
2	EVT--2012/11/28	P50-PW R-CPU_CORE	Value change / PR529, PR520, PR528, PR503, PR507, PR515, PR527, PR509, PR510, PR504, PC516, PL502, PC543, PC544, PC545, PC546, PC514, PC519	PW R	TPS51622 for 15W CPU setting
3	EVT--2012/11/28	P48-PW R-1.05VS_VCCP/1.8VSP	Value change / PR407, PR401, PR404, PR405, PC404, PC405	PW R	For TPS51362 design change
4	EVT--2012/11/28	P46-PW R-1.35VP/0.675VSP	Short pad reserve / PR163	PW R	
5	EVT--2012/11/28	P47-PW R-3VALW /5VALW	PC351 reserve / PC352 mount	PW R	ME lim itation
6	EVT--2012/11/28	P50-PW R-CPU_CORE	PC504 reserve	PW R	ME lim itation
7	EVT--2012/11/28	P44-PW R-BATTERY CONN / OTP	PF2 change vendor	PW R	for common design change
8	EVT--2012/11/29	P46-PW R-1.35VP/0.675VSP	change material / PL152	PW R	for common design change
9	DVT-2012/12/13	P43-PW R-DCIN	modify PB1101 footprint	PW R	for common design change
10	DVT-2012/12/13	P44-PW R-BATTERY CONN / OTP	modify PR20, PR21 pin define	PW R	for layout module request
11	DVT-2012/12/13	P46-PW R-1.35VP/0.675VSP	change PR160 to 8.06K	PW R	for output voltage level
12	DVT-2012/12/13	P46-PW R-1.35VP/0.675VSP	modify PL152, PC155, PR164 pin define	PW R	for layout module request
13	DVT-2012/12/13	P47-PW R-3VALW /5VALW	del PC331, PC351	PW R	ME lim itation
14	DVT-2012/12/13	P47-PW R-3VALW /5VALW	modify PL332, PR337, PR342, PR357 pin define	PW R	for layout module request
15	DVT-2012/12/13	P47-PW R-3VALW /5VALW	modify the VS_ON direction	PW R	input signal
16	DVT-2012/12/13	P48-PW R-1.05VS_VCCP/1.8VSP	change the 1.8VSP EN to 6511_PW R_EN	PW R	for High enable
17	DVT-2012/12/13	P48-PW R-1.05VS_VCCP/1.8VSP	modify PR401, PC402, PR182 pin define	PW R	for layout module request
18	DVT-2012/12/13	P49-PW R-1.5VALW P	change PR603 to 0ohm	PW R	VBST resistor
19	DVT-2012/12/13	P49-PW R-1.5VALW P	modify PR602, PR606, PL601 pin define	PW R	for layout module request
20	DVT-2012/12/13	P50-PW R-CPU_CORE	change the B+ EM I bead	PW R	ME lim itation
21	DVT-2012/12/13	P50-PW R-CPU_CORE	modify PC516, PR526, PR527, PC517, PR529, PR512, PR516, PR518, PR534, PR536, PR530, PR524 pin define	PW R	for layout module request
22	DVT-2012/12/13	P51-PW R-VGA_CORE	PR912/add 10K ohm	PW R	pull high +3VS_DGPU
23	DVT-2012/12/13	P51-PW R-VGA_CORE	PC934 change to 0.01u	PW R	VREF pull down cap
24	DVT-2012/12/13	P51-PW R-VGA_CORE	modify PL901, PR908, PR907, PR901, PR923, PR924, PR927, PC946, PR913, PR915, PR914, PR904, PR928, PR931, PR932, PR909 pin define	PW R	for layout module request
25	PVT-2013/01/25	P47-PW R-3VALW /5VALW	change PC332, PC352, PR409 location to PC331, PC351, PR335	PW R	for common design change
26	PVT-2013/01/25	P46-PW R-1.35VP/0.675VSP	change PL152 value from 1uH to 0.68uH	PW R	for common design change
27	PVT-2013/01/25	P46-PW R-1.35VP/0.675VSP	change PC157 to 390uF 5*5.7	PW R	layout request
28	PVT-2013/01/25	P51-PW R-VGA_CORE	change PC934 part number	PW R	for common design change
29	PVT-2013/02/04	P50-PW R-CPU_CORE	PC529, 531, 533, 534, 535, 537 reserve PC505 0.1uF change to 10nF PR527 4.99k change to 2.7k PR509 374k change to 309k PC506 0.15u change to 0.1u PR510 39k change to 56k	PW R	for TPS51622 date code 2BI design change
30	PVT-2013/02/04	P51-PW R-VGA_CORE	PC947 330u reserve	PW R	for common design change
31	PVT-2013/02/04	P51-PW R-VGA_CORE	PL903, 904 change PN	PW R	for common design change
32	PVT-2013/02/04	P49-PW R-1.5VALW P	net name change from 1.5VALW _EN to PCH_PW R_EN	HW	for common design change
33	PVT-2013/02/07	P49-PW R-1.5VALW P	PR604 PC608 mount	EM I	EM I request
34	PVT-2013/02/07	P49-PW R-1.5VALW P	PR603 change from 0ohm to 2.2ohm		
35	PVT-2013/02/07	P48-PW R-1.05VS_VCCP/1.8VSP	PL602 change from 4.7u to 2.2u	PW R	For design change
36	PreMP-2013/03/18	P46-PW R-1.35VP/0.675VSP	PL402 change PN from RX00 (H1.8) to 5K80 (H3.0)	PW R	change Material for useful height
37	PreMP-2013/03/18	P46-PW R-1.35VP/0.675VSP	PC157 footprint change to C_2	PW R	
38	PreMP-2013/03/18	P47-PW R-3VALW /5VALW	PR155 0 ohm resistor change to short pad	EM I	EM I request
39	PreMP-2013/03/18	P47-PW R-3VALW /5VALW	PR333, PR355 0 ohm resistor change to short pad	EM I	EM I request
40	PreMP-2013/03/18	P46-PW R-1.35VP/0.675VSP	PR164 0 ohm resistor change to short pad	HW	HW request
41	PreMP-2013/03/26	P49-PW R-1.5VALW P	PR602 change to 174kohm	PW R	adjust OCP setting
42	PreMP-2013/03/26	P51-PW R-VGA_CORE	PR914 change to 27kohm	PW R	Rem ove Richteck colay solution
43	PreMP-2013/03/26	P48-PW R-1.05VS_VCCP/1.8VSP	PR904, PC945, PR918, PR928 Rem ove		
44	PreMP-2013/03/26	P49-PW R-1.5VALW P	PL401 change PN	PW R	for common design change
45	PreMP-2013/03/26	P			

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					VSKTA	2.0	
				Date:	Friday, June 21, 2013	Sheet	52 of 57

HW PIR (Product Improve Record)

YSKTA LA-9865P Schematic Change List

REVISION: 0.1 to 0.2

Item	Date	Page	Solution	Request
1.	12/05	P37	Update CHG_CB1,0 level shifter (QR1) circuit	For USB S & C level shifter circuit
2.	12/05	P37	U5.1 (CHG_PWR_GATE#) was connected to the EC(GPIO49) Pin82	For USB S & C
3.	12/05	P40	Add pull high RB12 to +3VL on CHG_PWR_GATE#	For USB S & C
4.	12/05	P32	Add R66,R67 22ohm for CRT undershoot issue	For CRT VSYNC and HSYNC
5.	12/05	P18	Rotate DV1	For GC6
6.	12/05	P18	FB_CLAMP_MON be pulled up to +3VS_DGPU on RPV12.6	For GC6
7.	12/05	P22	Change UV2 from SA007320120 to SA007320300	For GC6
8.	12/05	P40	Change PM_SLP_S4# from UB1.127 to UB1.84	For EC GPIO setting
9.	12/05	P40	Change USB_EN#0 from UB1.84 to UB1.23.	For EC GPIO setting
10.	12/05	P40	Change FB_CLAMP from UB1.23 to UB1.127.	For EC GPIO setting
11.	12/06	P18	Change CV9,CV10,CV11,CV12,CV13,LV1 to OPT@	For DIS BOM config.
12.	12/06	P18	Change RV8 from OPT@ to DGCLK@	For DIS GCLK config.
13.	12/06	P18,34	Change 27M_R to VGA_X1	For VGA CLK
14.	12/06	P34	Change 27M to VGA_X1_R	For VGA CLK
15.	12/06	P31	Change RT128, RT130 to 0 ohm short pad.	For DP to CRT circuit
16.	12/06	P31	Change RT129, RT123 from CRT@ to @.	For DP to CRT circuit
17.	12/06	P31	Change RT140,RT141,RT138 to RP6 (75 ohm row resistor).	For DP to CRT circuit
18.	12/06	P31	Change RT121,RT126,RT143,RT144 to RP7 (4.7K ohm row resistor).	For DP to CRT circuit
19.	12/07	P09	Change RH17 from IEDP@ to LVDS@	For LVDS panel backlight control
20.	12/07	P09	Change RH18 from LVDS@ to IEDP@	For LVDS panel backlight control
21.	12/07	P29	Change R23,R24 from @ to mount	For SMBUS control by EC
22.	12/07	P29	Change R25,R26 from mount to @	For SMBUS control by EC
23.	12/07	P30	Change L64,L65,L66,L67 from SM070001S00 to SM070001R00.	For HDMI choke
24.	12/10	P08	Change UH3,UH4 from 45@ to always mount.	For DVT build
25.	12/10	P10	Change R274,R272 from mount to @	For touch pad function
26.	12/10	P29	Change UY3,CY26 from EHDMI@ to 8201@	For touch pad function
27.	12/11	P29	Delete RT125,RT127	For DP to CRT ISP programming data pin
28.	12/12	P38	Change CA51,CA52 from 2.2uF to 4.7uF	Follow Codec ALC269 common design
29.	12/13	P32	Delete R464,R465,R466	For CRT impedance matching resistors
30.	12/13	P30	Mirror vertically for L64,L65,L66,L67	For HDMI choke layout
31.	12/13	P27	Swap RP5 net name	For EDP row resistor layout
32.	12/17	P31	Swap RP6,RP7 net name	For DP to CRT row resistor layout
33.	12/18	P08	Delete UH4,RH96,RH97,RH92,RH93,RH94,CH10	Remove SPI ROM for Win8 (2MByte) circuit
34.	12/18	P08	Change UH3 from SA00003K820 to SA00006MK00	Change SPI ROM to 8MByte
35.	12/18	P08,40	Change EC_CS1# to EC_CS0#	For 8MB SPI ROM
36.	12/18	P08	Delete PCH_SPICS1#	For use 8MB SPI ROM
37.	12/18	P08	Change UH3.1 from PCH_SPICS1# to PCH_SPICS0#	For use 8MB SPI ROM
38.	12/20	P27	CT9 change to 10UF (the same as CT4)	For use 8MB SPI ROM
39.	12/20	P27	Delete LT3 and +SWR_LX then short +SWR_V12 to UT2.12	For LVDS Translator
40.	12/20	P27	Delete EC_SMB_CK3 and EC_SMB_DA3	For LVDS Translator
41.	12/20	P27	UT2 change to RTD2132R	For LVDS Translator
42.	12/20	P27	UT2 change 2132S@ to LVDS@	For LVDS Translator
43.	12/20	P27	Change UT2.15 from TL_ENVDD to +LCD_VDD	For LVDS panel control
44.	12/20	P27,28	Delete TL_ENVDD	For LVDS panel control
45.	12/20	P27	Delete RT106	For LVDS
46.	12/20	P28	Delete R429	For LVDS
47.	12/20	P27	Change RT4,RT7 from 2132S@ to @	For LVDS
48.	12/20	P27	Change RT6,RT12 from 2132R@ to LVDS@	For LVDS
49.	12/20	P28	Change U18,C475,R426,R430 from 2132S@ to IEDP@	For LCD power circuit
50.	12/20	P28	Delete C475,U18,R430,R426 IEDP symbol	For LCD power circuit
51.	12/20	P29	Change UY3 symbol from SA00005CW00 to SA00005CW10	For HDMI re-driver

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REVISION: 0.1 to 0.2

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VSKTA LA-9865P Schematic Change List

REVISION: 0.2 to 0.3

Item	Date	Page	Solution	Request
1.	01/21	P38,40	Add EC_MUTE_INT	For audio codec
2.	01/21	P31	Update ISPSCL /ISPSDA connection	For CRT
3.	01/30	P18,40	UV1 GPIO12 (GPS_DOWN#) be connected to EC GPXIOA01	For GPS
4.	01/30	P28	Change L61 form TOUCH@EMI@ change to TOUCH_EMI@	For EMI BOM Config
5.	01/30	P32	Change L68,L69,L70,C503,C504,C505,C506,C507,C508 form CRT@EMI@ change to CRT_EMI@	For EMI BOM Config
6.	02/01	P28	Delete R426 and change U18.1 connected to +LCD_VDD	For LVDS
7.	02/01	P28	Delete R427 and change U18.3 connected to LCD_ENVDD	For LVDS
8.	02/01	P40	Change UB1.81 from PCIE_WAKE# to TRANS_SEL, and add pull-high resistor RB26 and reserve RB25 to GND	For LVDS
9.	02/01	P35	PCIE_WAKE# add R4279 and reserve R4283 to LAN_WAKE# to EC	For WAKE function
10.	02/01	P9	Change RH171 from 10Kohm to 1Kohm	For WAKE function
11.	02/01	P9	Delete RH136 and change U1.AJ5 from PCIE_WAKE#_R to WAKE# and connected to R4279.1 and RH171.1	For WAKE function
12.	02/01	P35	Add RC284 between JWLAN.1 to WLAN_WAKE#	For WAKE function
13.	02/01	P28	Add DA8 on INT_MIC_CLK	For ESD's request
14.	02/01	P28	Add DA9 on INT_MIC_DATA	For ESD's request
15.	02/01	P28	Reserve D97 on USB20_P7_R, USB20_N7_R	For ESD's request
16.	02/04	P10	Reserve D98 to GND on H_THERMTRIP#	For ESD's request
17.	02/04	P41	Reserve D99 to GND for ON/OFFBTN#	For ESD's request
18.	02/04	P28	Delete R427 and U18.3 connected to LCD_ENVDD	For LVDS
19.	02/04	P28	Add R4280, R4281 to co-layout L61	For LVDS
20.	02/04	P40	Change RB135,RB136 BOM config from LVDS@ to @	For LVDS
21.	02/08	P29	Change RY33 from 4.99Kohm to 4.3Kohm	For HDMI test
22.	02/08	P42	Change RM4 from 100Kohm to 10Kohm	For WLAN issue
23.	02/08	P38	Change RA41, CA53 from @EMI@ to EMI@	For EMI 216MHz noise (24MHz harmonic).
24.	02/08	P40	Change QB1 from SB000009080 to SB570020020	For EL code
25.	02/21	P28	Change L61 from TOUCH_EMI@ to @TOUCH_EMI@	For EMI touch
25.	02/21	P28	Add R4280,R4281 on USB20_P5/USB20_N5	For EMI touch
26.	02/23	P36	Change RW2 from 0ohm to 33ohm	For EMI's request
27.	02/23	P36	Change CW9 BOM config from @EMI@ to EMI@.	For EMI's request
28.	02/23	P31	Change YT1 from SJ10000DK00 to SJ100009700	For crystal vendor's recommend
29.	02/23	P28,35,37	Change L61,L62,LR5,LR7,LR8 from SM070000K00 to SM070001N00.	For EMI's request
30.	02/23	P30	Change L64,L65,L66,L67 from SM070001R00 to SM070001N00.	For EMI's request
31.	02/23	P37	Change L56,L60,L71,L72 from SM070001U00 to SM070001R00.	For EMI's request
32.	02/23	P38,40	Add EC_MUTE_INT on UA1.48 and connected RB38 to UB1.122	For audio codec
33.	02/23	P9,40	Change UB1.123 from CLK_EC to CLK_EC_R and connected to RB7 and a reserve resistor RB5; and RB5 connected to CLK_EC; and RB7 connected to POK	For CLK_EC and POK
34.	02/27	P31	Change RT118, RT119, RT115, RT116 from @ to CRT@.	For DP to CRT vendor's recommend

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YSKTA LA-9865P Schematic Change List

REVISION: 0.3 to 1.0

Item	Date	Page	Solution	Request
01.	03/04	P27	Add EC_SMB_CK3,EC_SMB_DA3 circuit	For LVDS translator SMBUS
02.	03/04	P28,37	Swap L56,L60,LR7,L71,L72,LR8,L62,L61 for layout	For layout routing
03.	03/04	P31	Change RT123, RT129 from CRT@ to @	For DP to CRT translator
04.	03/05	P40	Change CLK_EC_R to POK_R	For Power's request
05.	03/05	P36	Add RW5,RW6,RW7,RW8 on SD_DATA for EMI request	For CardReader
06.	03/05	P10	RP35 (10K) change to RP9 (2.2K)	For pull-high row resistor
07.	03/05	P41	Change SW2 to @	For Pre-MP BOM
08.	03/05	P36	Change RW1 to short pad	For reduce part count
09.	03/05	P07	Change R163 to short pad	For reduce part count
10.	03/05	P34	Change RC284 to short pad	For reduce part count
11.	03/05	P38	Change RA27,RA28,RA65,RA68 to short pad	For reduce part count
12.	03/05	P07	Change R32 to short pad	For reduce part count
13.	03/07	P08	Add RH79 for PCH_SMBCLK pull high	For SMBUS
14.	03/07	P31	Add RT147 and update YT1 symbol	For DP to CRT translator
15.	03/08	P08	Change RP8 to 10K	For pull-high row resistor
16.	03/11	P36	Modify CardReader circuit	For CardReader
17.	03/11	P41	Change WLAN/WiMAX LED power plane from +5VS to +5VLAW	For WLAN/WiMAX LED
18.	03/11	P36	Change LW1-LW6 to SM010005X00	For EMI part
19.	03/11	P41	Add BOM structure for WLAN LED	For BOM config.
20.	03/13	P36	Change CW7 from 2.2u to 4.7u	For CardReader
21.	03/13	P40	Change LAN_WAKE# from UB1.108 to UB1.71	For WAKE
22.	03/13	P09,35,40	Change WAKE# to EC_SWI# and connect to UB1.108	For WAKE
23.	03/14	P12	Change C18 footprint from C_D2 to C_D2-S	For layout's request
24.	03/14	P05,10,41	Change CH7,D98,D99 BOM config from @ESD@ to ESD@	For ESD's request
25.	03/14	P40	Change CB14 BOM config from @ to ESD@	For ESD's request
26.	03/18	P05,40	Change CH7, CB14 from 180PF to 0.1UF	For ESD's request
27.	03/18	P10,41	Change D98,D99 to CH12, CH13	For ESD's request
28.	03/18	P05	Change CH11 from 180PF to 100PF	For ESD's request
29.	03/18	P40	Change CB13 from 100PF to 0.1UF	For ESD's request
30.	03/18	P33,09,41,07,08,31	Change R27,R65,R471,R472,RH26,RH42,RT114 to 0ohm short-pad resistor	For reduce part count
31.	03/19	P36	Change CW13,CW12,CW11,CW10,CW9 from 10PF to 4.7PF	For EMI request
32.	03/19	P36	Change CW14 from @EMI@ to EMI@	For EMI request
33.	03/19	P40	Add RR8 then connected to CB0_WAKE# and LAN_WAKE#	For LAN_WAKE#
34.	03/19	P40	Change UB1.71 from LAN_WAKE# to CB0_WAKE#	For USB Sleep and Charge
35.	03/19	P40	Add RR9 then connected to CB0_WAKE# and EC_CB0	For USB Sleep and Charge
36.	03/19	P40	UB1.97 connected to EC_CB1	For USB Sleep and Charge
37.	03/19	P37	Change RR2 and RR3 from 0ohm to 0ohm short-pad	For USB Sleep and Charge
38.	03/19	P37	Add RR6 then connected to CHG_CB0 and EC_CB0	For USB Sleep and Charge
39.	03/19	P37	Add RR7 then connected to CHG_CB1 and EC_CB1	For USB Sleep and Charge
40.	03/19	P37	Add RB11 on EC_CB0 then pull-high to +3VALW_PCH	For USB Sleep and Charge
41.	03/19	P37	Add RB13 on EC_CB1 then pull-high to +3VALW_PCH	For USB Sleep and Charge
42.	03/20	P28	Change U50 BOM config from IEDP@ to always mount	For LVDS issue
43.	03/20	P28	Change R436 BOM config from LVDS@ to @	For LVDS issue
44.	03/20	P32	Change C503,C504,C505,C506,C507,C508 BOM config from CRT_EMI@ to CRT@	For CRT BOM ocnfig
45.	03/20	P40,35,13,28	Change RB7,R4279,R210,R4280,R4281,RR9 to 0ohm short pad	For reduce part count
46.	03/20	P40,37	Change RR8,RR2,RR3 to 0 ohm	For option
47.	03/22	P37	Change RR6, RR7 from un-mount to mount	For EC controls USB S & C
48.	03/23	P41	Change MB DA8 P/N from DA8000XK000 to DA8000XK010	For Pre-MP BOM
49.	03/23	P35,37	Change U13,U15 from SA00004KB00 to SA00003TV00	For power switch issue on Rosetta
50.	03/26	P05	Change C74,C76,C77,C80 BOM config to CRT	For CRT BOM config.
51.	03/26	P37	Change RB11,RB13 from un-mount to mount	For EC controls USB S & C
52.	05/09	P37	Add CPU R1 & R3 PN in ISPD sheet	For CPU BOM config.
53.	06/11	P41	Add GPU N14P-GV2 R1 & R3 PN in ISPD sheet	For GPU BOM config.
54.	06/11	P42	Change Q6 PN from SB570020110 to SB000000EN00	For X1 code
55.	06/11	P30	Change Q190,Q191 PN from SB501110010 to SB000000PF00	For main source
56.	06/11	P38	Change RA66 PN from SM01000CY00 to SM01000I000	For X1 code
57.	06/11	P31	Change RT123, RT129 from @ to mount	For DP to CRT translator (vendor's recommend)
58.	06/11	P08	Change C2 from 12pF to 22pF	For Pre-MP issue
59.	06/11	P08	Change C2 BOM config from NOGCLK@ to mount	For Pre-MP issue
60.	06/11	P08	Change R48,Y2,C3 BOM config from NOGCLK@ to @	For BOM config.



Vinfix

HW PIR (Product Improve Record)

VSKTA LA-9865P Schematic Change List

REVISION: 1.0 to 2.0

Item	Date	Page	Solution	Request
01.	06/20	P31	Change RT117 from CRT@ to always mount	For ZRMAA issue
02.	06/21	P08	Change RH42 from 0ohm short pad to 0ohm and always mount	For HDD lost issue

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